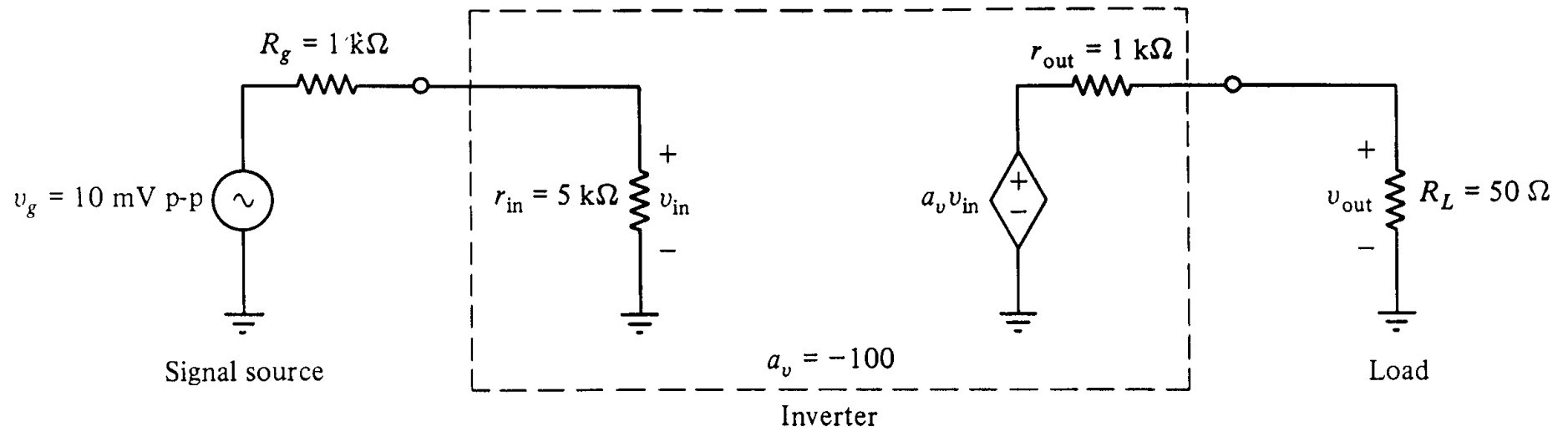


# Multistage and Power Amplifiers

- Compared to single stage amplifier, multistage amplifiers provide increased input resistance, reduced output resistance, increased gain, and increased power handling capability
- Multistage amplifiers commonly implemented on integrated circuits where large numbers of transistors with common (matched) parameters are available
- Typical inverter (Common Emitter) has moderately large gain and has input and output resistances in the Kilohm range
- Follower configuration has much higher input resistance, lower output resistance but has only unity gain
- Amplifier requires the desirable features of both configurations



**Figure 12.1** Linear model of a single-stage inverter connected to signal source and load.

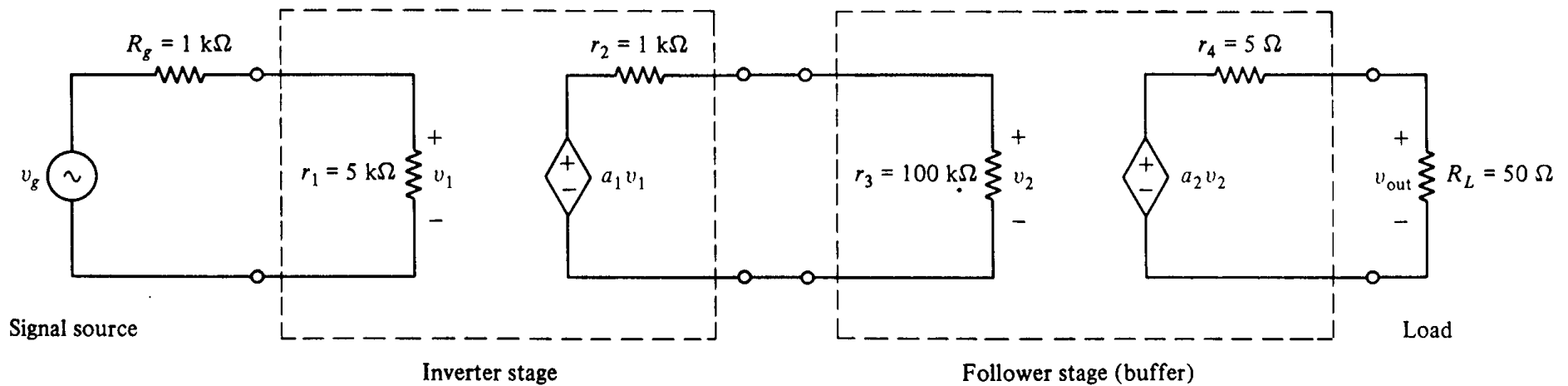
$$v_{IN} = v_g \frac{r_{IN}}{r_{IN} + R_g} = 0.83 v_g$$

$$v_{OUT} = a_v v_{IN} \frac{R_L}{R_L + r_{OUT}} \cong -4.0 v_g$$

# Two Port Amplifier Cascade

- Impact of input and output loading can be minimized by cascading two amplifiers

Figure 12.2 Cascaded amplifier consisting of inverter stage and follower stage.



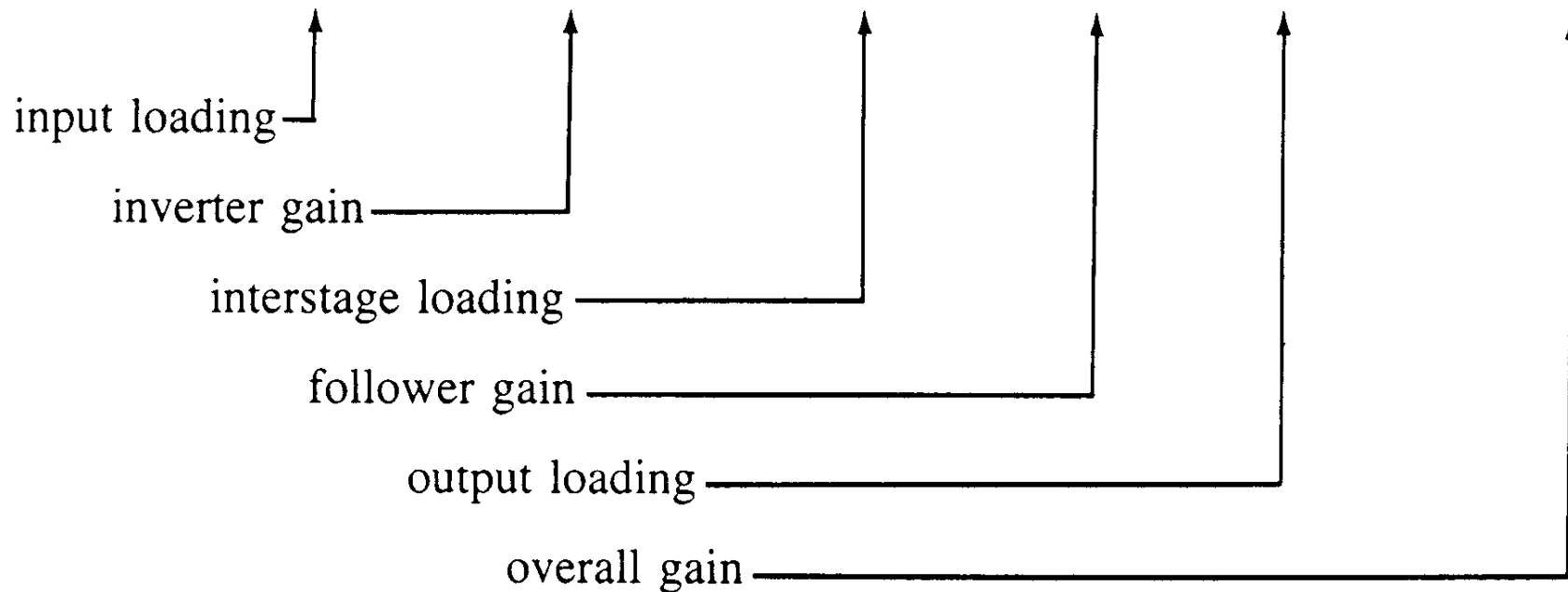
$$\begin{aligned}
 v_{\text{out}} &= (a_2 v_2) \frac{R_L}{R_L + r_4} \\
 &\quad \downarrow \\
 &= \underbrace{(a_1 v_1) \frac{r_3}{r_3 + r_2}}_{\downarrow} a_2 \frac{R_L}{R_L + r_4} \\
 &= v_g \frac{r_1}{r_1 + R_g} \frac{a_1 r_3}{r_3 + r_2} \frac{a_2 R_L}{R_L + r_4}
 \end{aligned}$$

**(12.5)**

For these values, the overall cascade gain (12.5) becomes

$$\frac{v_{out}}{v_g} = \left( \frac{5 \text{ k}\Omega}{5 \text{ k}\Omega + 1 \text{ k}\Omega} \right) (-100) \left( \frac{100 \text{ k}\Omega}{100 \text{ k}\Omega + 1 \text{ k}\Omega} \right) (1) \left( \frac{50 \Omega}{50 \Omega + 5 \Omega} \right) \quad (12.7)$$

$$= (0.83) (-100) (0.99) (1) (0.91) \approx -75$$



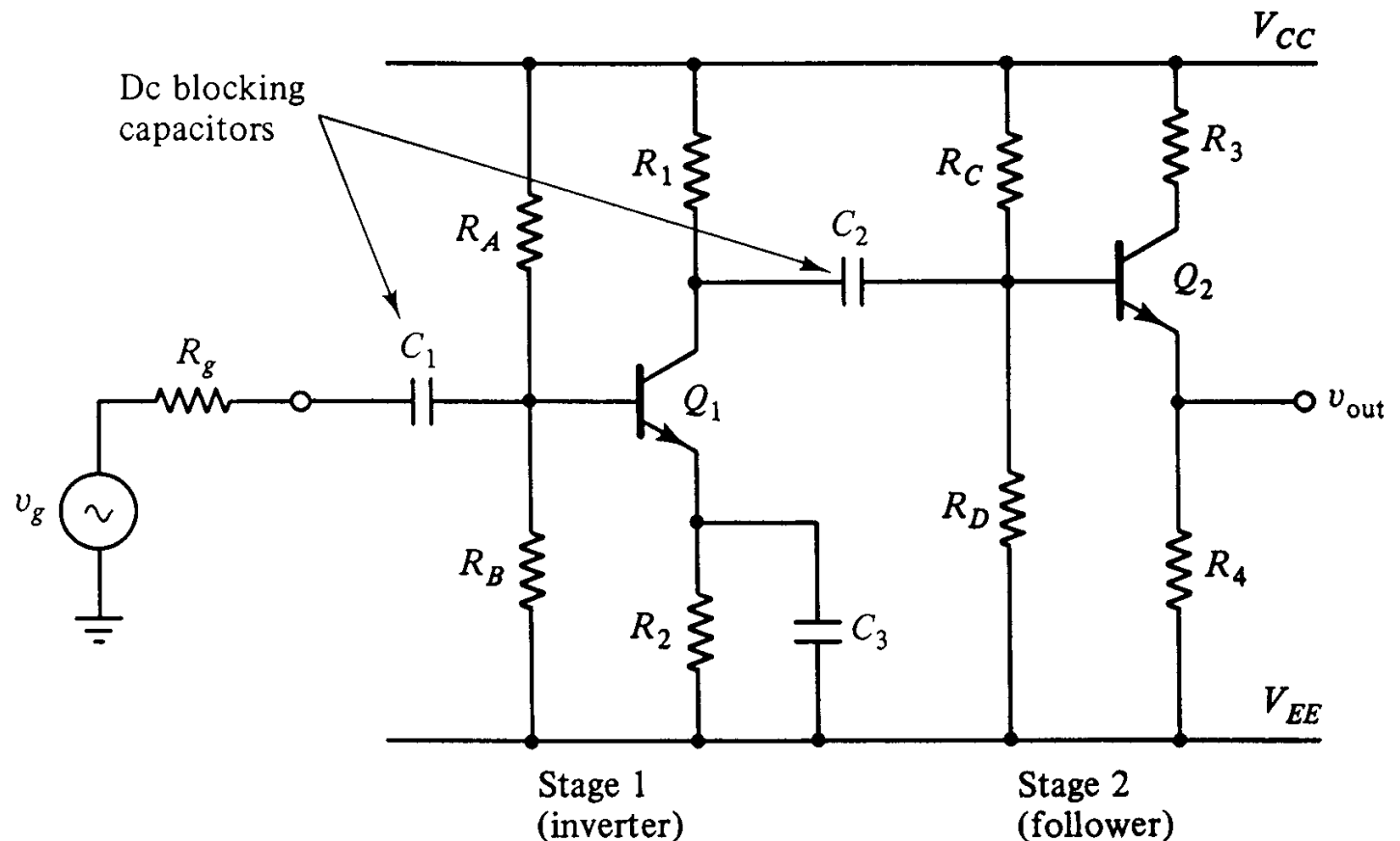
- Multistage cascading is used to create amplifiers with high input resistance, low output resistance and large gains

# Multistage Amplifier Biasing

- It is possible to create multistage cascade where each stage is separately biased and coupled to adjacent stages via DC blocking capacitors

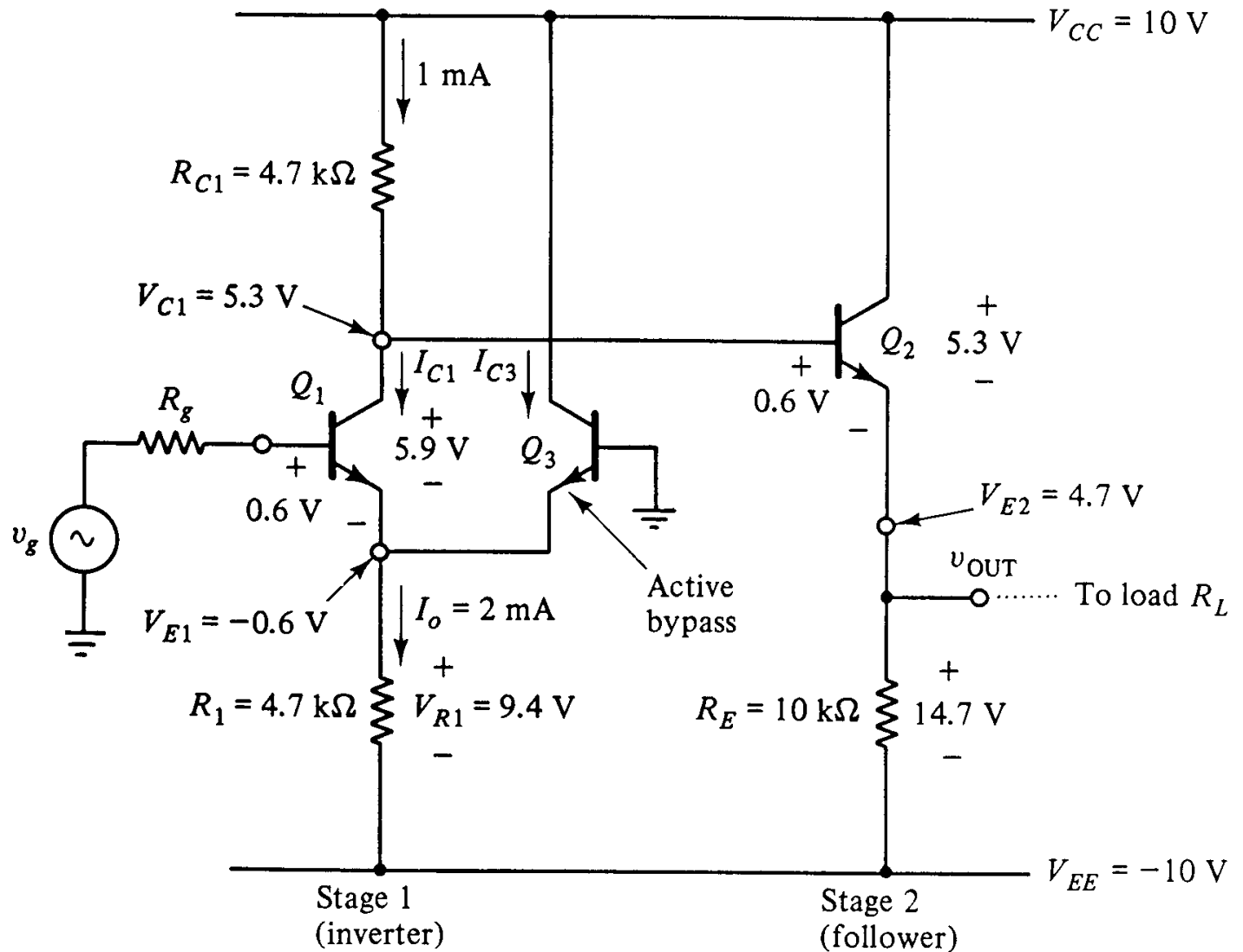
**Figure 12.3**

Possible implementation of the two-stage inverter-follower cascade. This design technique is not optimal because it uses many discrete capacitors.



- Amplifier gain is reduced at low frequencies
- Difficult to build integrated circuits with large value blocking capacitors
- DC coupled amplifier

**Figure 12.4**  
Two-stage dc-coupled cascaded amplifier.



## Small Signal Model of Cascaded Amplifier

### Inverter

If  $R \gg R_{TH}$  Looking into the emitter of  $Q_3$

$$r_{IN1} = r_{p1} + r_{p3} = 2r_{p1}$$

$$r_{OUT1} = R_{C1}$$

$$a_1 = \frac{-\beta_{o1} R_{C1}}{r_{p1} + r_{p3}} = \frac{-g_{m1} R_{C1}}{2} \quad (\text{Midband Gain})$$

- Assuming matched devices and  $r_o$  of  $Q_1$ ,  $Q_2$  and  $Q_3$  is large enough to be ignored



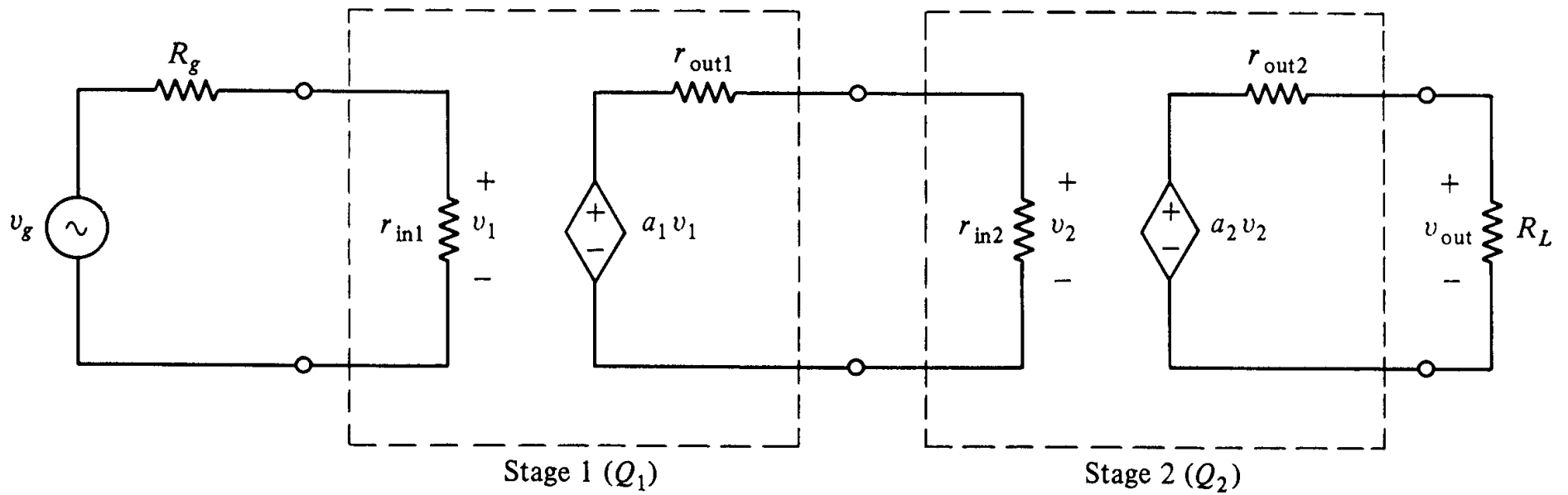
## Follower (Stage 2)

$$r_{IN2} = r_{p2} + (b_{o2} + 1)R_E \quad (\text{Without } R_L \text{ Connected})$$

$$r_{OUT2} = R_E \parallel \frac{r_{OUT1} + r_{p2}}{b_{o2} + 1}$$

$$a_2 = \frac{(b_{o2} + 1)R_E}{r_{p2} + (b_{o2} + 1)R_E}$$

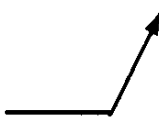
Figure 12.5 Equivalent cascade model of the amplifier of Fig. 12.4.



$$\frac{v_{out}}{v_g} = a_1 a_2 \frac{r_{in1}}{R_g + r_{in1}} \frac{r_{in2}}{r_{out1} + r_{in2}} \frac{R_L}{R_L + r_{out2}} \quad (12.21)$$

Substituting the expressions (12.15) through (12.20) into this equation yields

$$\frac{v_{out}}{v_g} = \frac{-\beta_{o1} R_{C1}}{r_{\pi1} + r_{\pi3}} \times \frac{(\beta_{o2} + 1) R_E}{r_{\pi2} + (\beta_{o2} + 1) R_E} \times \frac{r_{\pi1} + r_{\pi3}}{R_g + r_{\pi1} + r_{\pi3}}$$

stage 1 gain  stage 2 gain  input loading factor 

$$\times \frac{r_{\pi2} + (\beta_{o2} + 1) R_E}{R_{C1} + r_{\pi2} + (\beta_{o2} + 1) R_E} \times \frac{R_L}{R_L + r_{out2}} \quad (12.22)$$

interstage loading factor  output loading factor 

Cancellation of factors in numerator and denominator in Eq. (12.22) leads to

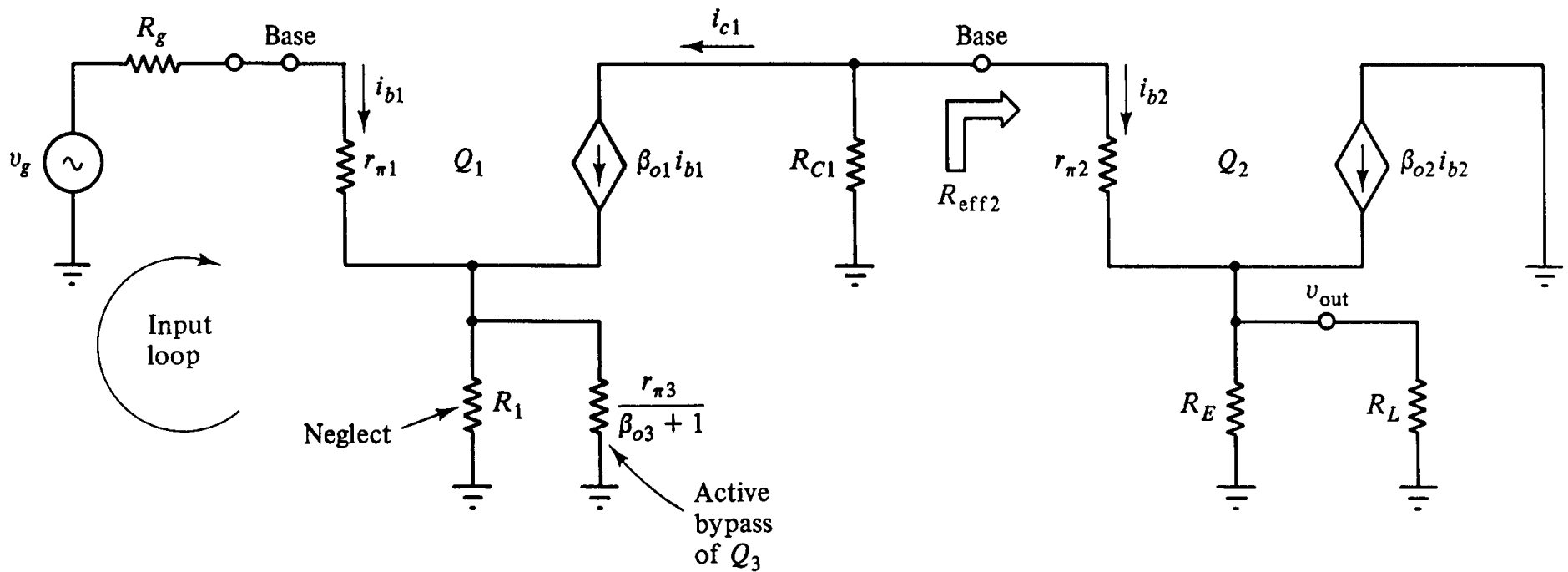
$$\frac{v_{out}}{v_g} = \frac{-\beta_{o1} R_{C1} (\beta_{o2} + 1) R_E}{(R_g + r_{\pi1} + r_{\pi3}) [R_{C1} + r_{\pi2} + (\beta_{o2} + 1) R_E]} \frac{R_L}{R_L + r_{out2}} \quad (12.23)$$

- Including this factor in the gain expression (12.23) yields the overall amplifier gain when the load resistor  $R_L$  is connected:

$$\frac{v_{\text{out}}}{v_g} = \frac{-\beta_{o1}R_{C1}(\beta_{o2} + 1)(R_E \parallel R_L)}{(R_g + r_{\pi1} + r_{\pi3})[R_{C1} + r_{\pi2} + (\beta_{o2} + 1)(R_E \parallel R_L)]} \quad (12.26)$$

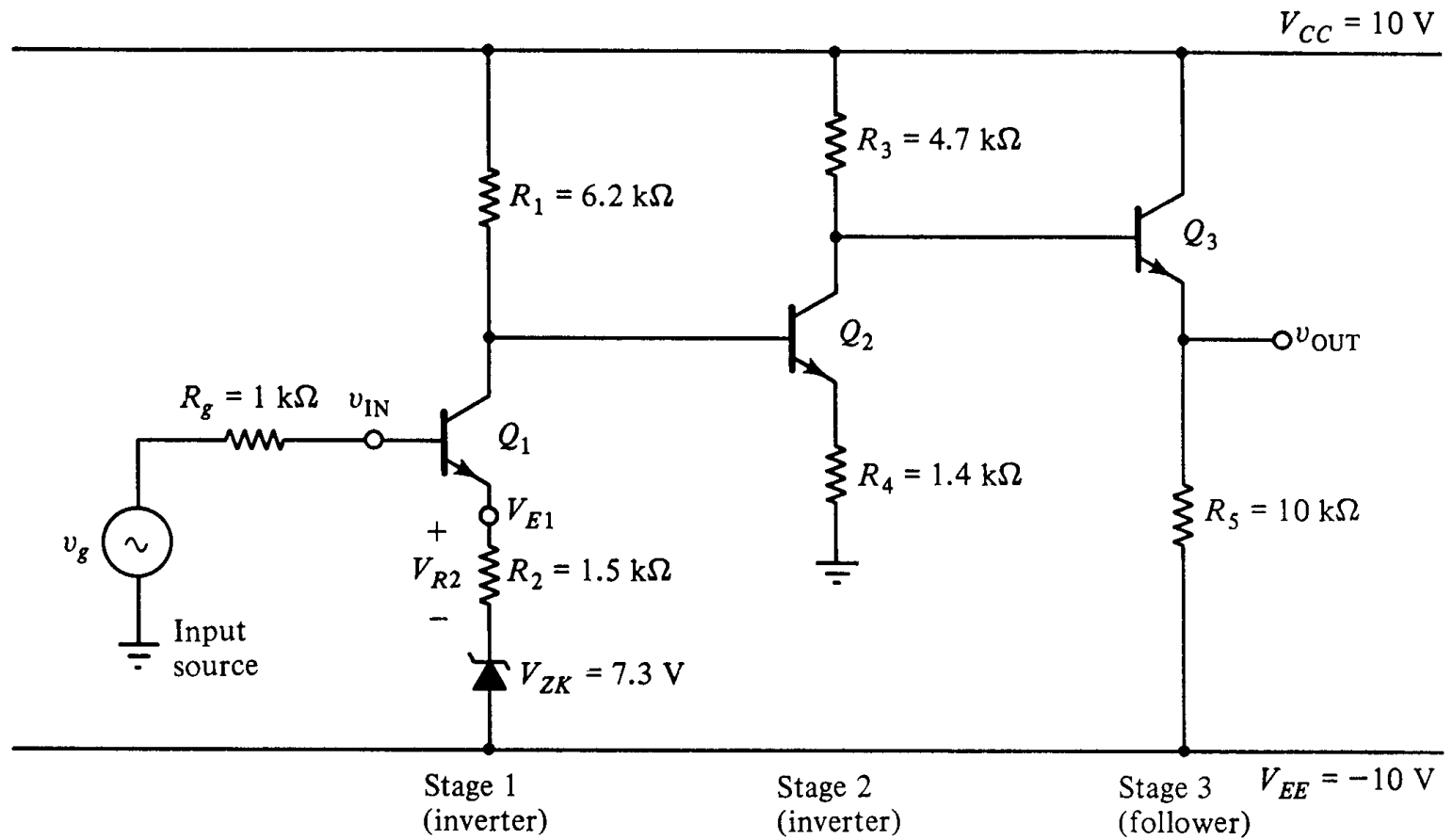
- The amplifier gain can also be derived from the complete small signal model

Figure 12.6 Complete small-signal model for the circuit of Fig. 12.4.



Example:

**Figure 12.7**  
Three-stage dc-coupled cascaded amplifier.



**TABLE 12.1** Gain and Resistance Parameters of the Cascade of Fig. 12.7

Parameter	Stage 1	Stage 2	Stage 3
$a_v$	$\frac{-\beta_{o1}R_1}{r_{\pi1} + (\beta_{o1} + 1)R_2} \approx \frac{-R_1}{R_2}$	$\frac{-\beta_{o2}R_3}{r_{\pi2} + (\beta_{o2} + 1)R_4} \approx \frac{-R_3}{R_4}$	$\frac{(\beta_{o3} + 1)R_5}{r_{\pi3} + (\beta_{o3} + 1)R_5} \approx 1$
$r_{in}$	$r_{\pi1} + (\beta_{o1} + 1)R_2 \approx \beta_{o1}R_2$	$r_{\pi2} + (\beta_{o2} + 1)R_4 \approx \beta_{o2}R_4$	$r_{\pi3} + (\beta_{o3} + 1)R_5 \approx \beta_{o3}R_5$
$r_{out}$	$R_1$	$R_3$	$R_5 \left\  \frac{r_{\pi3} + R_3}{\beta_{o3} + 1} \right.$

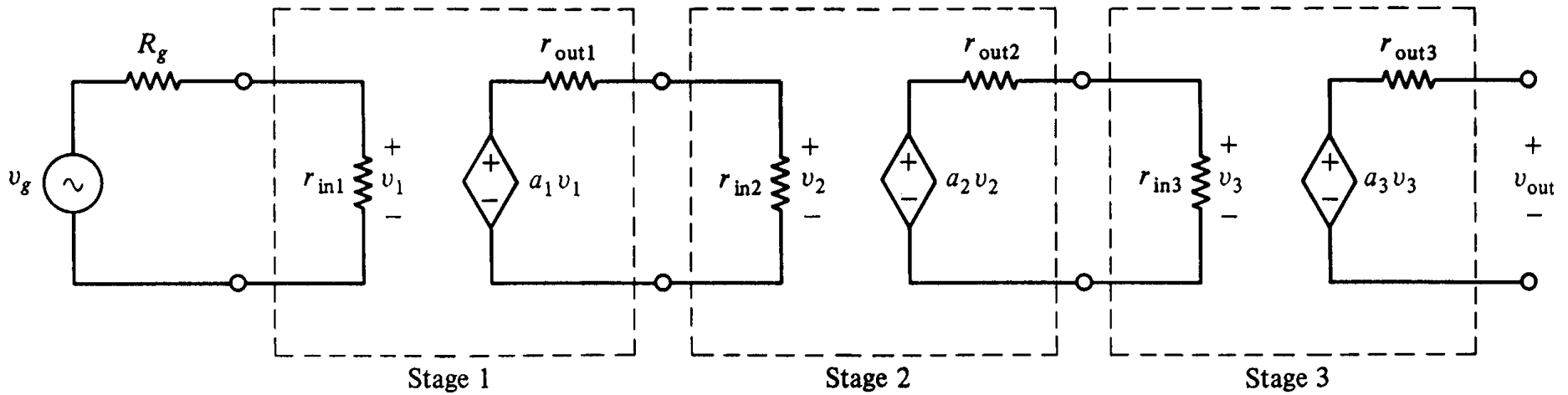


Figure 12.8 Two-port cascade of the amplifier of Fig. 12.7.

$$\frac{v_{\text{out}}}{v_g} = (a_1) (a_2) (a_3) \frac{r_{\text{in1}}}{R_g + r_{\text{in1}}} \frac{r_{\text{in2}}}{r_{\text{in2}} + r_{\text{out1}}} \frac{r_{\text{in3}}}{r_{\text{in3}} + r_{\text{out2}}}$$

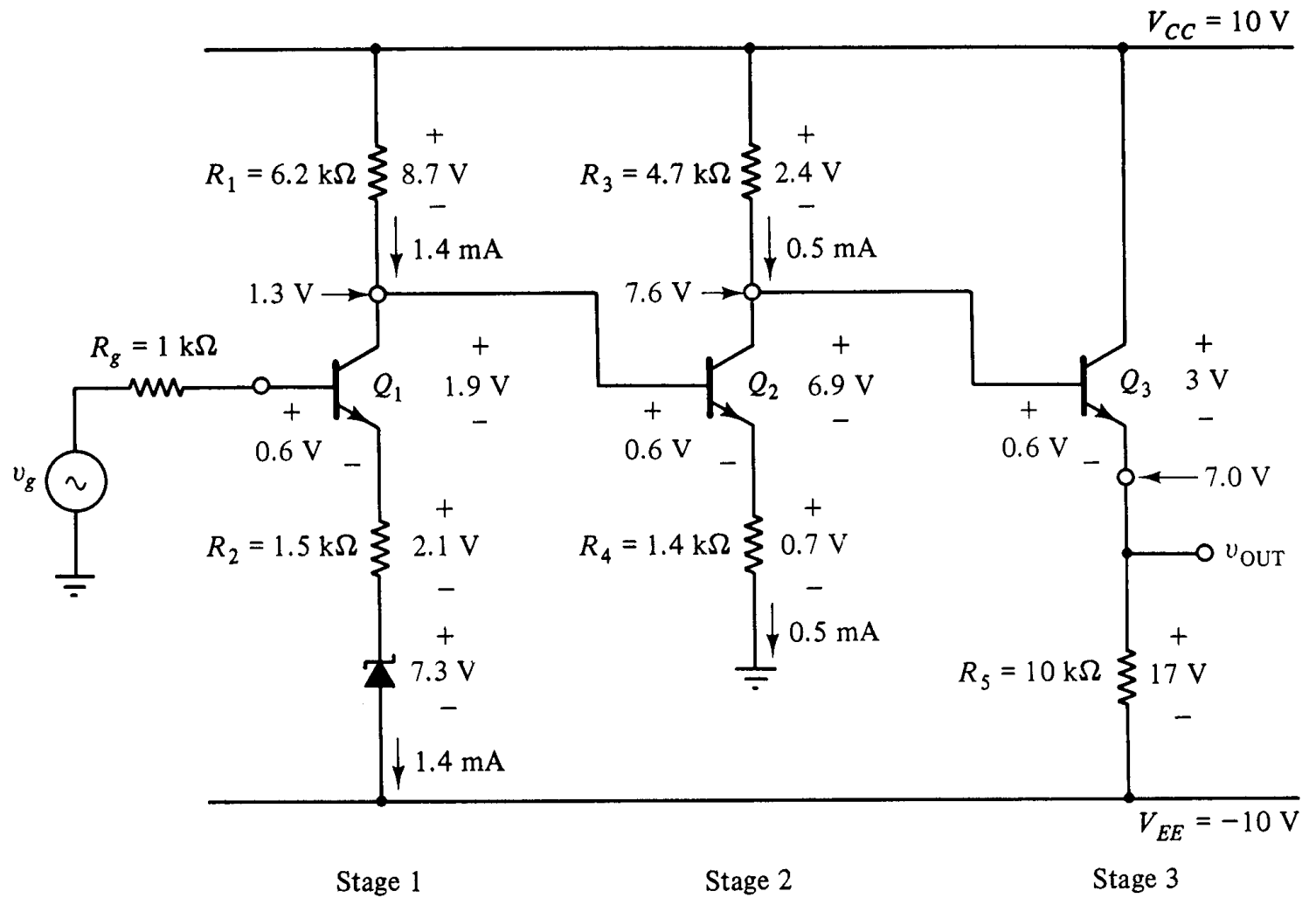
$$\simeq \frac{-R_1}{R_2} \frac{-R_3}{R_4} (1) \frac{\beta_{o1} R_2}{R_g + \beta_{o1} R_2} \frac{\beta_{o2} R_4}{R_1 + \beta_{o2} R_4} \frac{\beta_{o3} R_5}{R_3 + \beta_{o3} R_5} \quad (12.36)$$



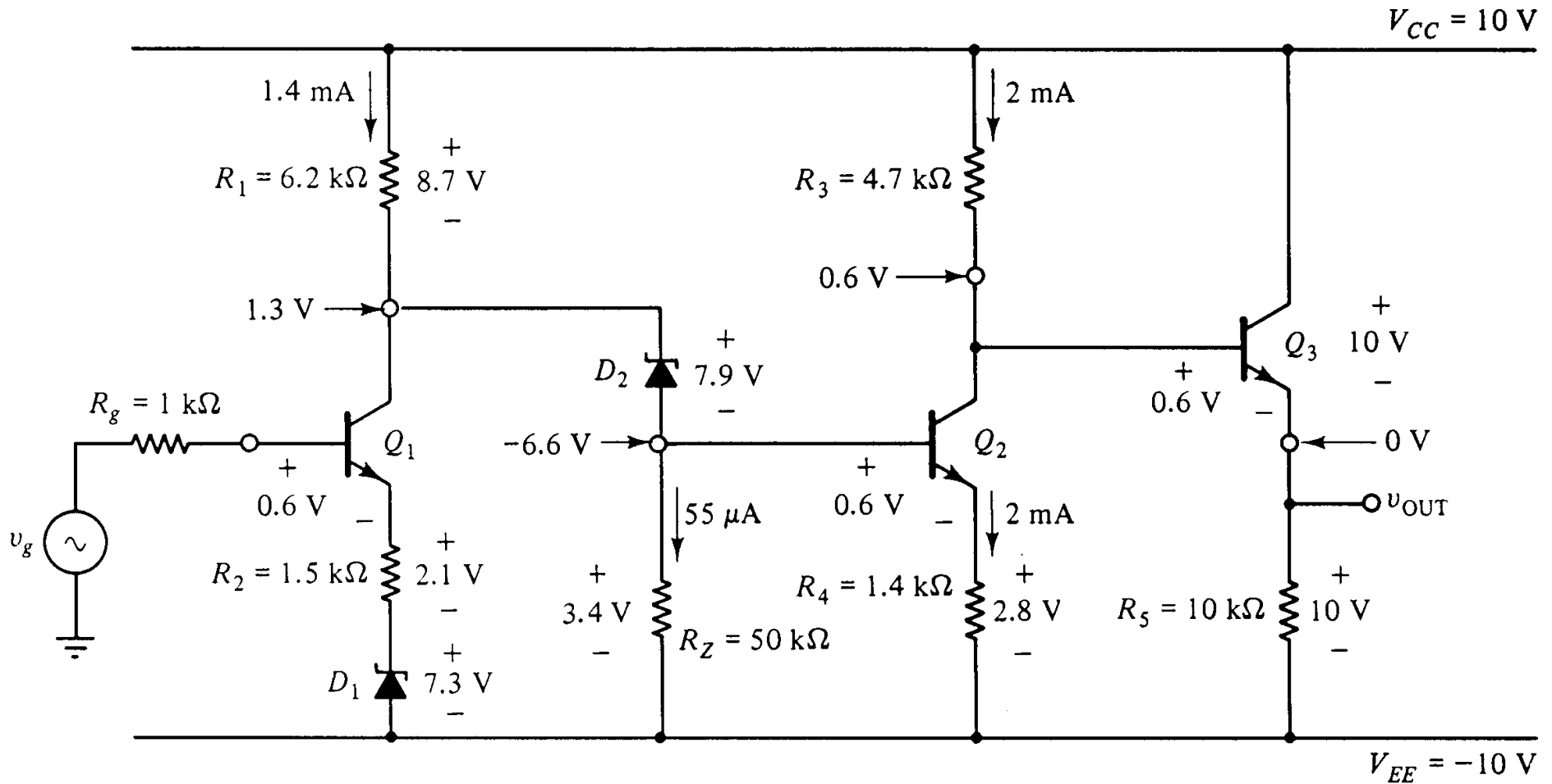
## DC Level Shifting

- In DC - coupled multistage cascade the output bias level of each stage increases to maintain the collector more positive than the base (constant current operation)
- If this voltage “stacking” is severe, little swing room is left in the final stages of the cascade

**Figure 12.9**  
 Multistage cascade of  
 Fig. 12.7 with dc bias  
 voltages indicated.



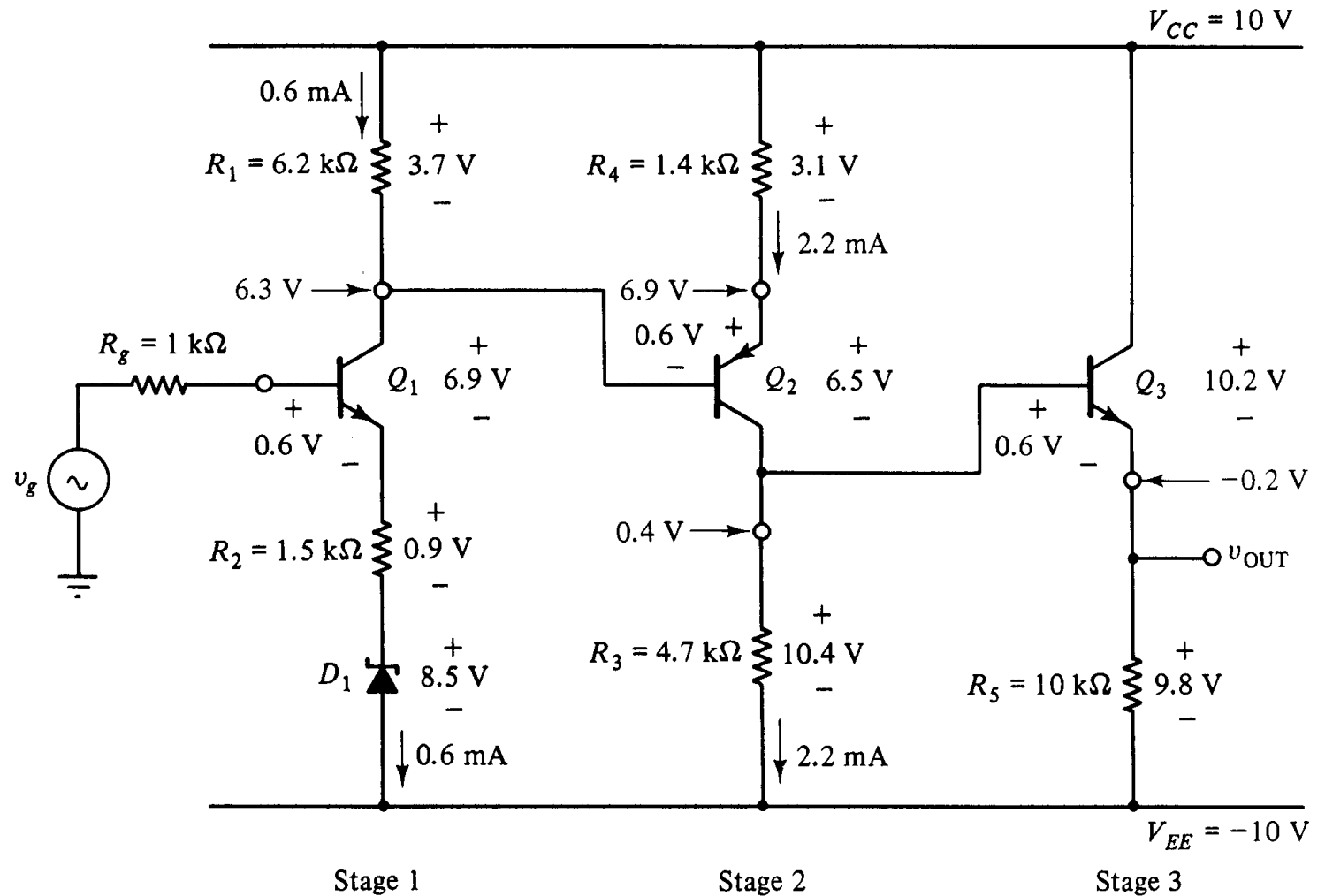
- Voltage stacking can be alleviated by the use of DC level shifting
- Level shifting alters the bias distribution but not the gain
- Simple method involves the insertion of a passive device with a constant DC voltage drop



**Figure 12.10** Zener diode level shifter added to the circuit of Fig. 12.9. BJT base currents are neglected in computing the indicated bias levels.

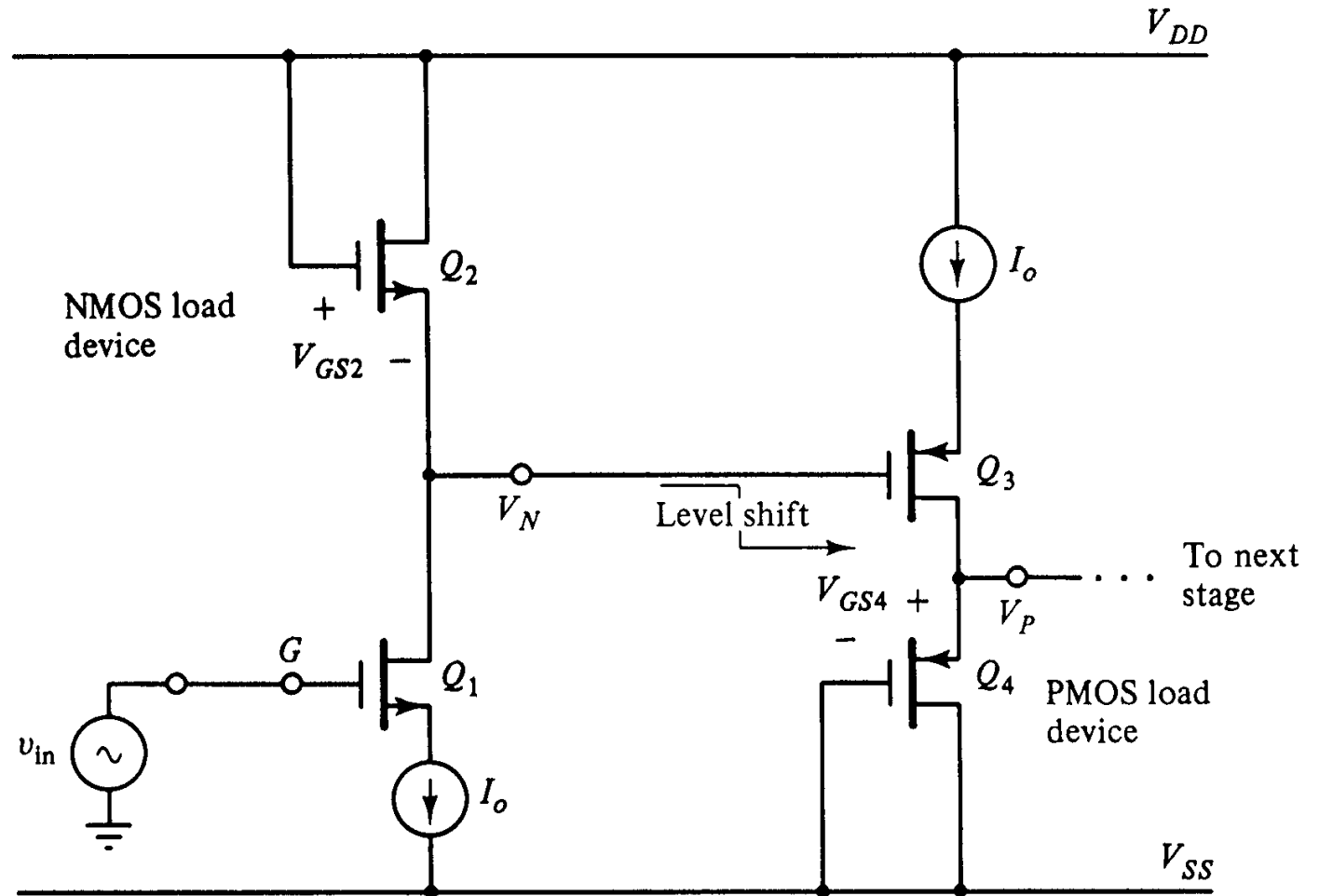
- By using complementary devices, active level shifting can be combined with amplification

**Figure 12.11**  
PNP level shifter  
incorporated into the  
circuit of Fig. 12.9. BJT  
base currents are  
neglected in  
computing the  
indicated bias levels.



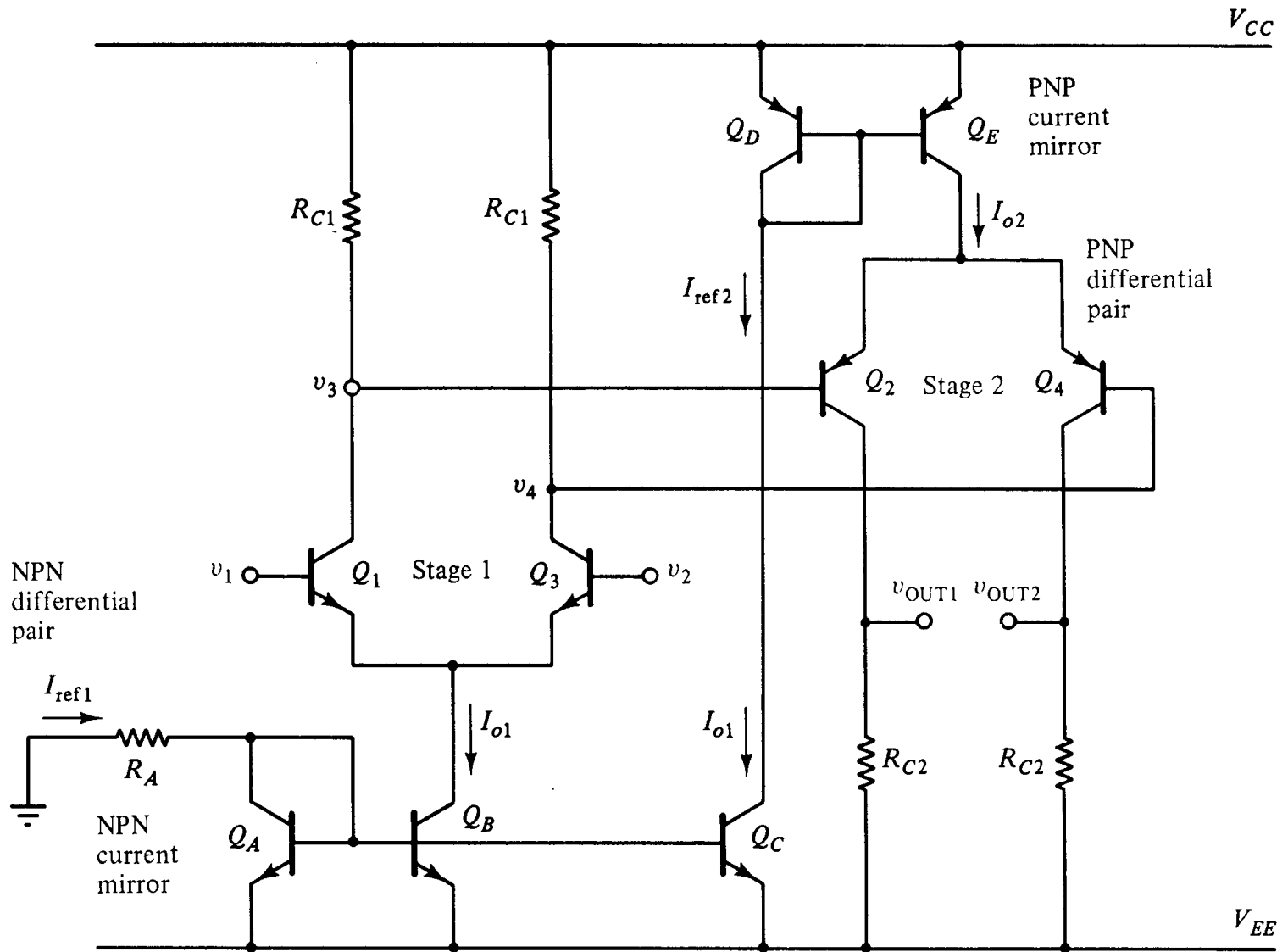
- In MOSFET circuits, DC level shifting is implemented using complementary NMOS and PMOS devices

**Figure 12.12**  
Complementary  $n$ -channel and  $p$ -channel MOSFET multistage amplifier cascade.



# Differential Cascade

**Figure 12.13**  
Two-stage BJT differential amplifier cascade with complementary NPN and PNP devices.



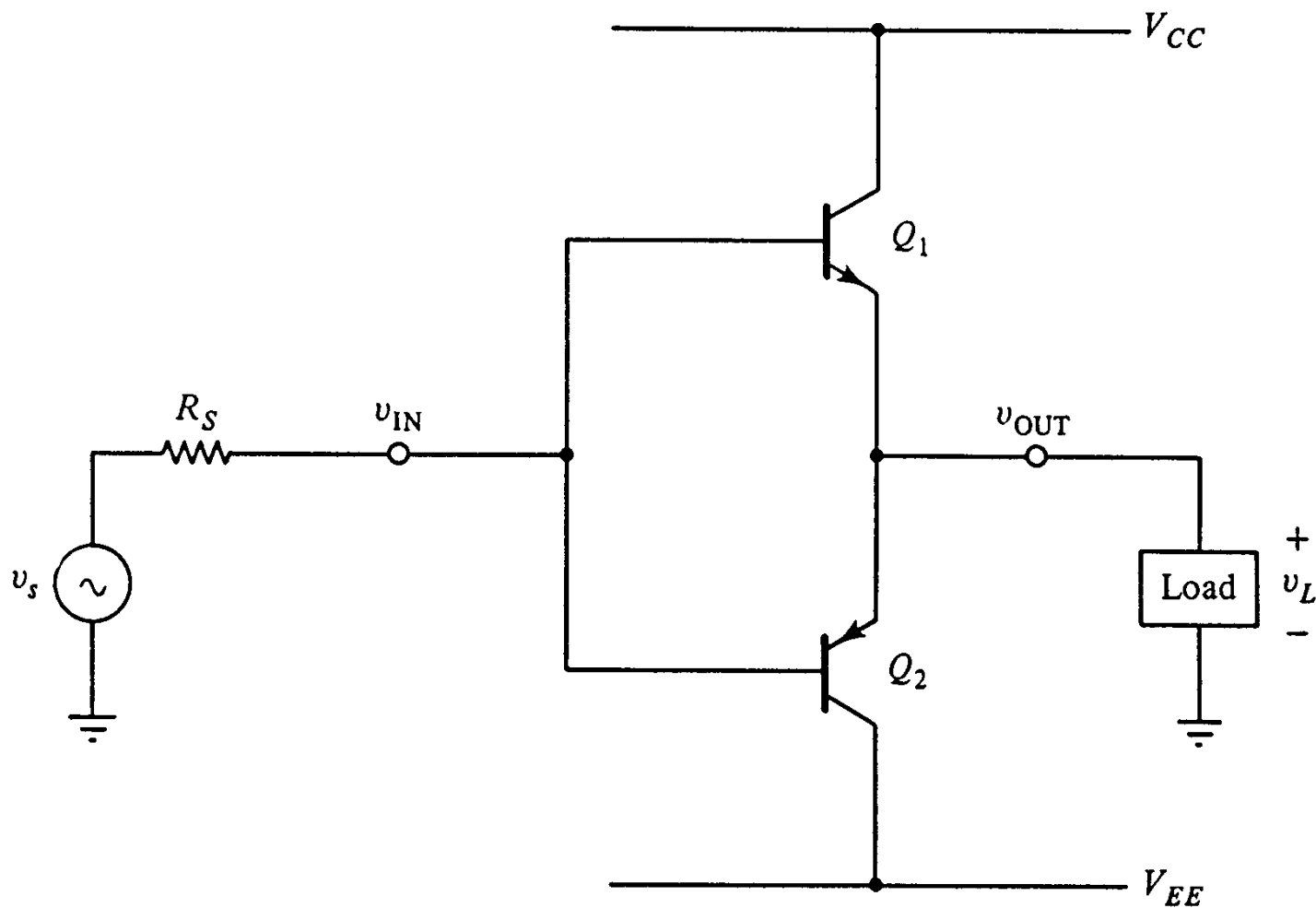
# Power Amplification Stages

- In many designs an amplifier is required to deliver large amounts of power to a passive load. The power may be a large current to a small resistance or a large voltage to a moderate resistance (impedance)
- Using a linear amplifier the power wasted in the active device is comparable to the power delivered to the load. Devices in the output stage must be capable of dissipating this excess power
- Alternative configurations offer increased efficiency at the expense of true linear operation

## Complementary Pair (Class B) Output

- When an amplifier is required to deliver large load currents it is desirable to bias the voltage of its output terminal near ground. This minimizes the bias power dissipated in both the load element and the active devices of the output stage

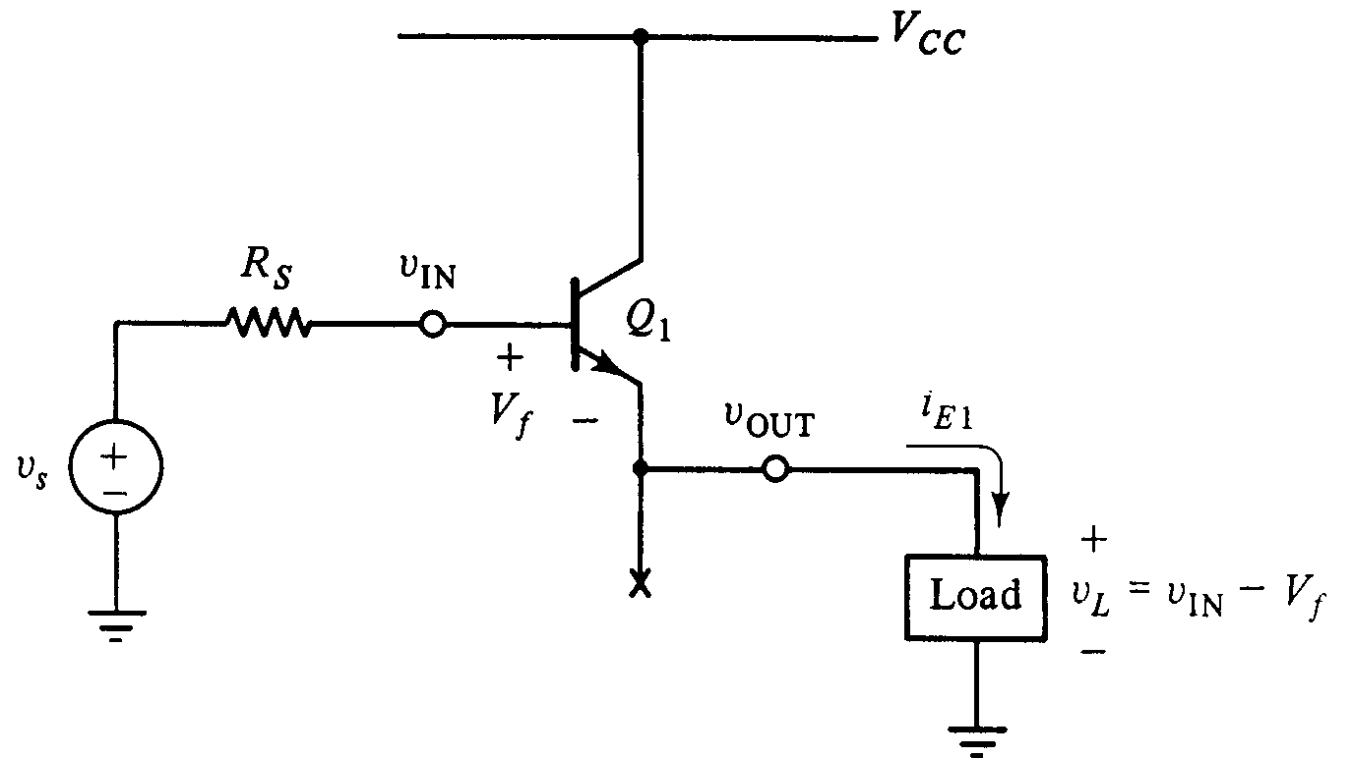
**Figure 12.17**  
Complementary-pair  
“push-pull” amplifier  
output stage made  
from BJTs. This circuit  
is a class B amplifier  
since neither device is  
biased in its active  
region.



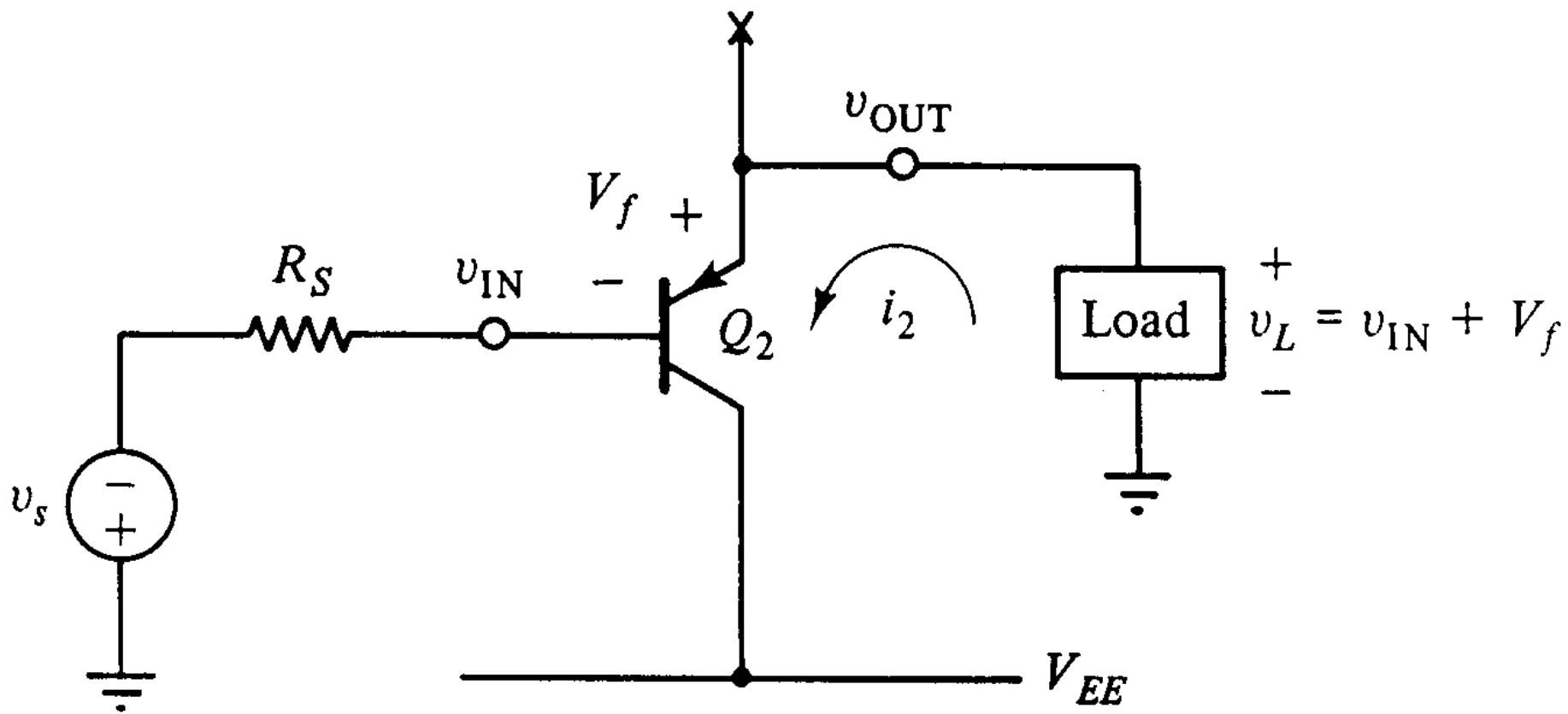


**Figure 12.18**

Operation of complementary-pair BJT follower for (a) positive ( $v_{IN} > V_f$ ) and (b) negative ( $v_{IN} < -V_f$ ) polarities of  $v_{IN}$ . When  $|v_{IN}| < V_f$ , both  $Q_1$  and  $Q_2$  are in cutoff and  $v_L = 0$ .



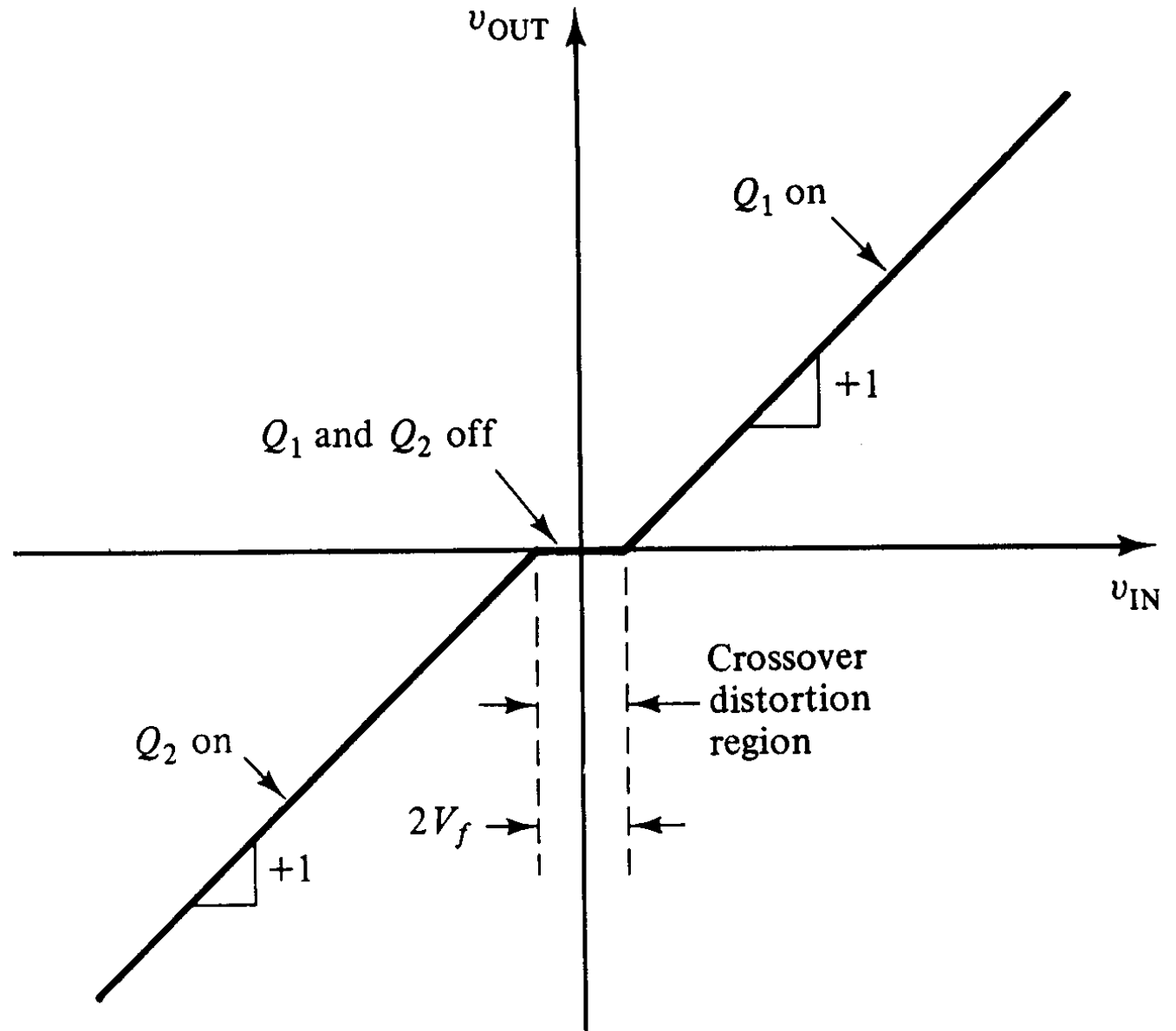
(a)



(b)

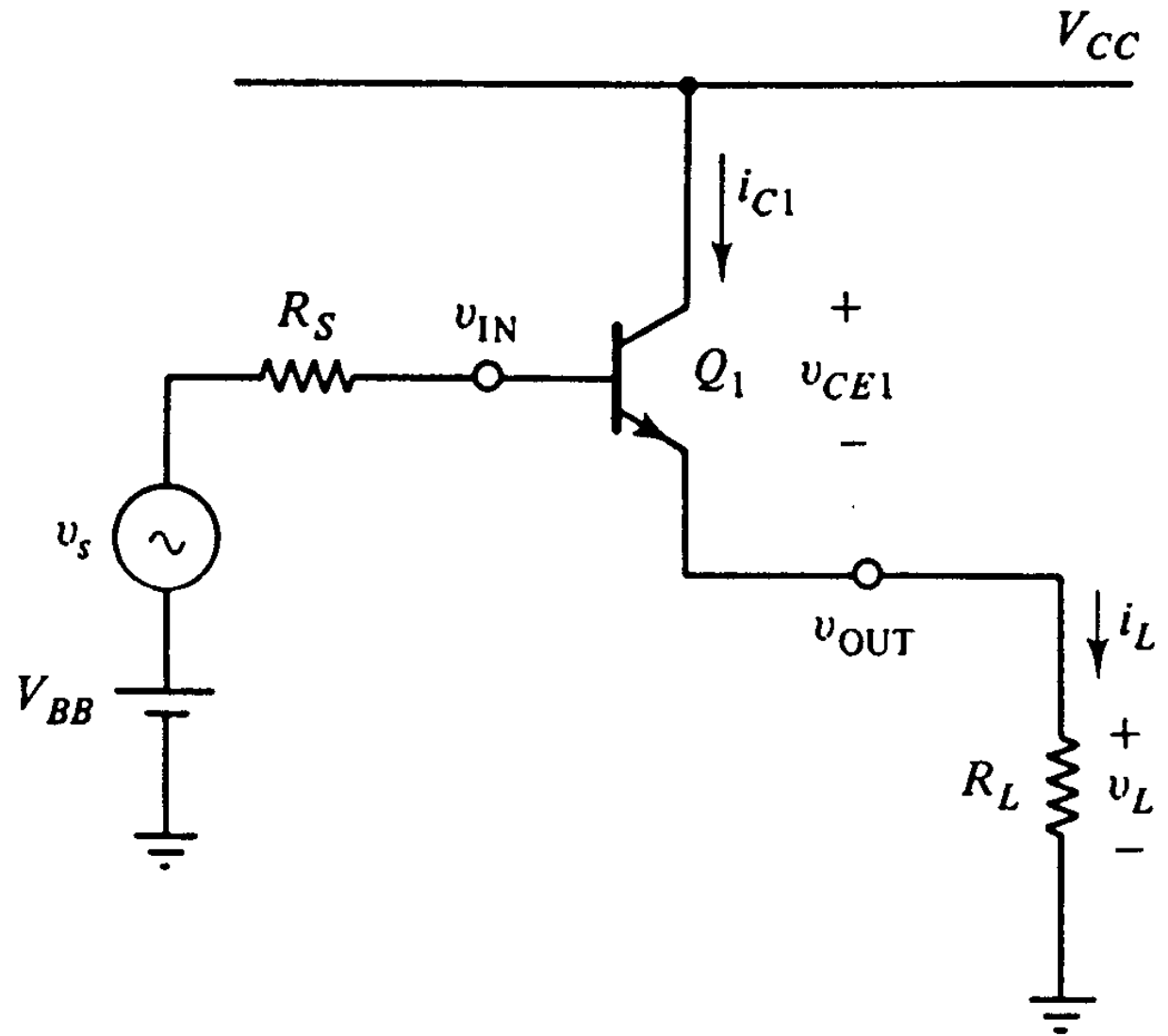
**Figure 12.19**

Large-signal transfer characteristic of the BJT circuit of Fig. 12.17. The crossover distortion region has a width of  $2V_f$ . The slope of the transfer characteristic outside this region is approximately equal to +1.



## Linearly Biased (Class A) Output

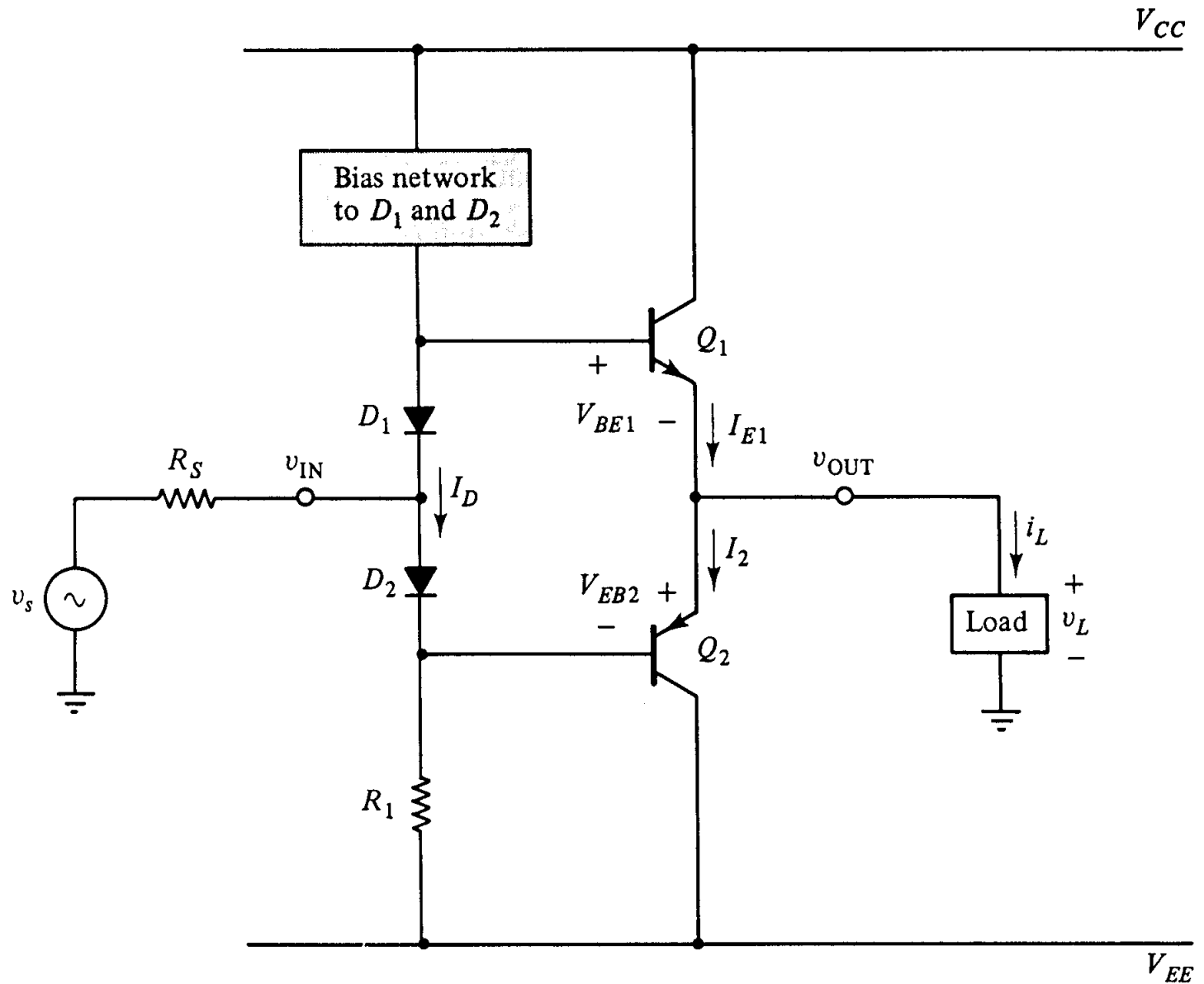
**Figure 12.20**  
One-transistor BJT follower stage. The voltage  $V_{BB}$  represents the dc bias voltage fed from the stage preceding the output stage.



# Minimally Biased (Class AB) Output

**Figure 12.21**

Circuit of Fig. 12.17 with diodes added to the base circuit. These diodes bias  $Q_1$  and  $Q_2$  slightly in the active region, forming a class AB amplifier.

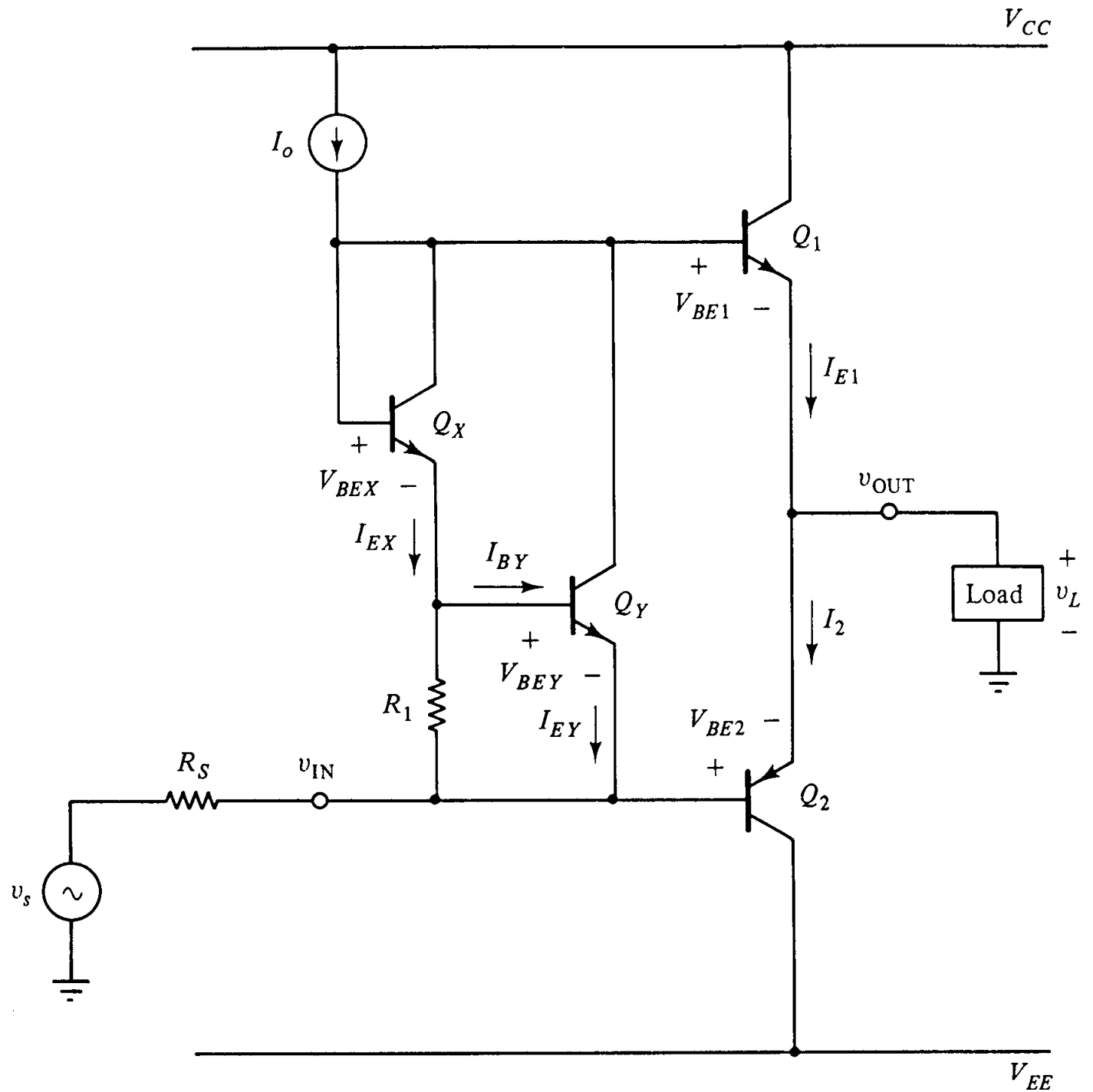


Example:

For the following circuit find the bias currents in  $Q_1$  and  $Q_2$  when  $I_O = 200 \mu\text{A}$ ,  $I_{EO} = 0.8 \times 10^{-11} \text{ mA}$ ,  $R_1 = 40 \text{ k}\Omega$ .

Assume base currents are negligible.

**Figure 12.22**  
Biasing diodes are replaced by BJTs  $Q_X$  and  $Q_Y$ .



Assume  $V_{BEY} = 0.6 V$   $I_{EX} \cong \frac{V_{BEY}}{R_1} = \frac{0.6 V}{40 k} = 15 \text{ mA}$

$$I_{EY} \cong 185 \text{ mA}$$

$$V_{BEY} = h V_T \ln \frac{I_{EY}}{I_{EO}} = (1)(0.025) \ln \frac{185 \text{ mA}}{0.8 \times 10^{-11} \text{ mA}} = 0.597 V$$

$$V_{BEX} = h V_T \ln \frac{I_{EX}}{I_{EO}} = 0.534 V$$

$$V_{BE1} = V_{BE2} = \frac{V_{BEX} + V_{BEY}}{2} = 0.565 V$$

$$I_{E1} = I_2 = I_{EO} \left( e^{v_{BE} / h V_T} - 1 \right) \cong (0.8 \times 10^{-11} \text{ mA}) \exp \left( \frac{0.565 V}{0.025 V} \right) = 53 \text{ mA}$$

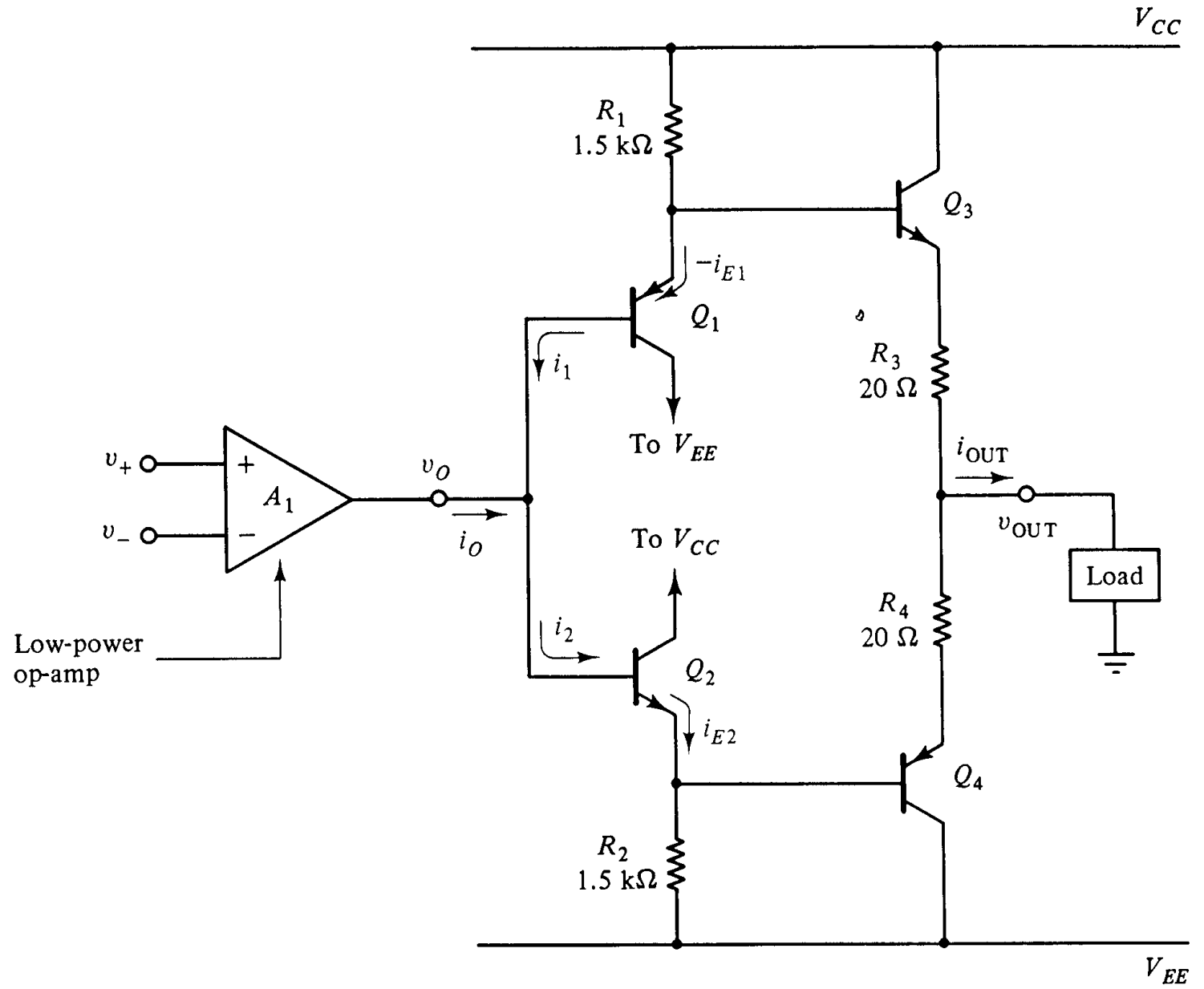


# Integrated Circuit Power Amplifiers

- A high power device can safely dissipate the heat generated by a large amount of electrical power
- Power amplifiers typically use such high powered devices
- Opamp combined with power amp forms high power opamp which can be connected in usual opamp feedback configurations
- If components are all fabricated on a single chip result is “Integrated circuit power amplifier”
- Advantage of integrated power amp is reduced size and simplicity of use

**Figure 12.23**

Simplified version of the LH0101 IC power amplifier. All the components shown would be contained on a single IC chip. (Reprinted with permission of National Semiconductor.)



Example:

Consider figure 12.23 with  $v_{OUT}$  connected to  $v_-$  and  $v_{IN}$  connected to  $v_+$  find the output current  $i_O$  of the low power opamp  $A_1$  as a function of the output voltage  $v_O$ . Assume  $V_{EE} = -V_{CC}$ .

Solution:

Circuit as connected will function as a voltage follower.

$$v_- = v_{OUT} = v_+ = v_{IN}$$

$$i_O = i_2 - i_1$$

$$i_O \cong \frac{(v_O - V_F) - V_{EE}}{b_{F2} R_2} - \frac{V_{CC} - (v_O + V_F)}{b_{F1} R_1}$$

$$V_{EE} = -V_{CC}, R_1 = R_2, b_{F1} = b_{F2}$$

$$i_O = \frac{2v_O}{b_{F1} R_1}$$

Example: If  $b_F = 20$ ,  $v_{OUT} = 5V$ ,  $R_{LOAD} = 50\Omega$  Estimate  $i_{OUT}$  and  $i_O$

Solution: 
$$i_{OUT} = \frac{v_{OUT}}{R_{LOAD}} = \frac{5V}{50\Omega} = 100 \text{ mA}$$

$$v_O \cong v_{OUT} \quad \text{Why ?}$$

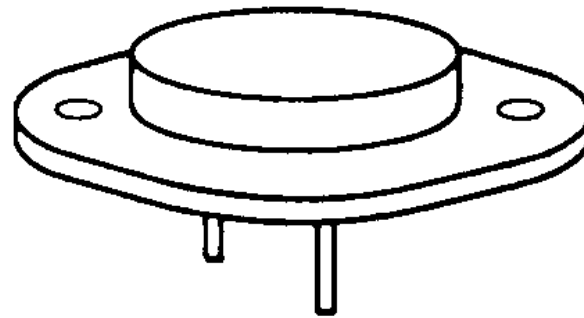
$$i_O = \frac{2v_O}{b_F R_1} = \frac{2(5V)}{(20)(1.5k\Omega)} = 0.33 \text{ mA}$$

Class AB power amp current gain is  $\cong 300$

# Power Devices

- When large amounts of power are delivered to an amplifier load some power will always be dissipated in the transistors of the amplifier
- Power amplifier stage must use specially fabricated power devices capable of safely handling the electrical power dissipated as heat
- Typical device has a large surface area and is mounted in good thermal ambient surroundings

**Figure 12.25**  
Typical high-power  
device packages.

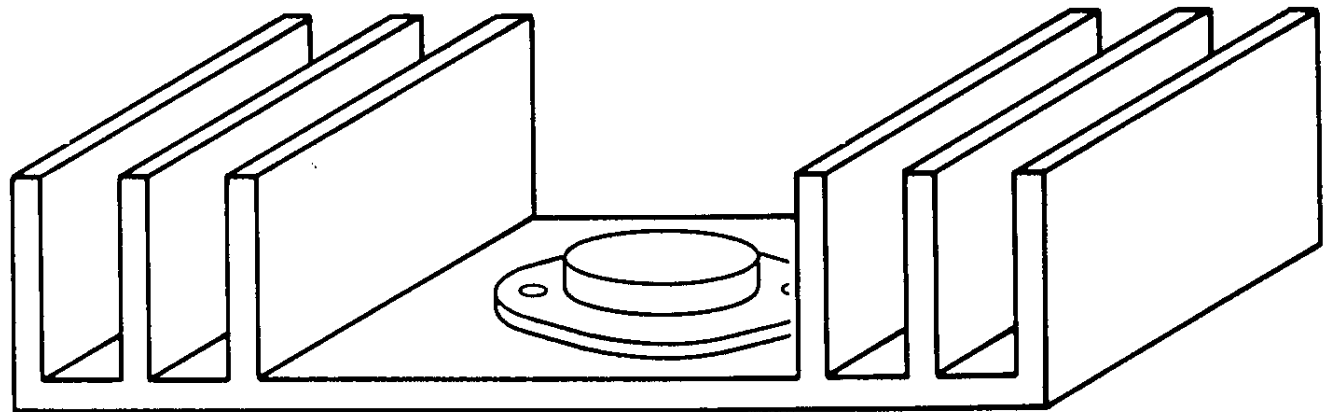


# Heat Sinks

- High power devices are often mounted on metal heat sinks which enhance the overall thermal contact and increase the removal of heat from the devices

**Figure 12.26**

Metallic heat sink used to improve the thermal conductivity between a power device and the surrounding air.



- A given heat sink is characterized by the heat transfer coefficient or thermal resistance  $\theta$  which describes the flow of heat from the sink to ambient air for a given rise in heat sink temperature
- The flow of heat is expressed as energy flow per unit time and has units of watts

$$P_{OUT} = \frac{T_{SINK} - T_{AIR}}{\theta}$$

- To improve thermal conduction, heat sinks may be coated with a thermally conductive compound
- If the overall thermal resistance between the transistor case and the heat sink is designed as  $\theta_{CASE-SINK}$

$$P_{OUT} = \frac{T_{CASE} - T_{AIR}}{\theta_{CASE-SINK} + \theta_{SINK-AIR}}$$

- The temperature of the semiconductor device will be higher than the case

$$P_{OUT} = \frac{T_{DEVICE} - T_{AIR}}{\theta_{DEVICE-CASE} + \theta_{CASE-SINK} + \theta_{SINK-AIR}}$$

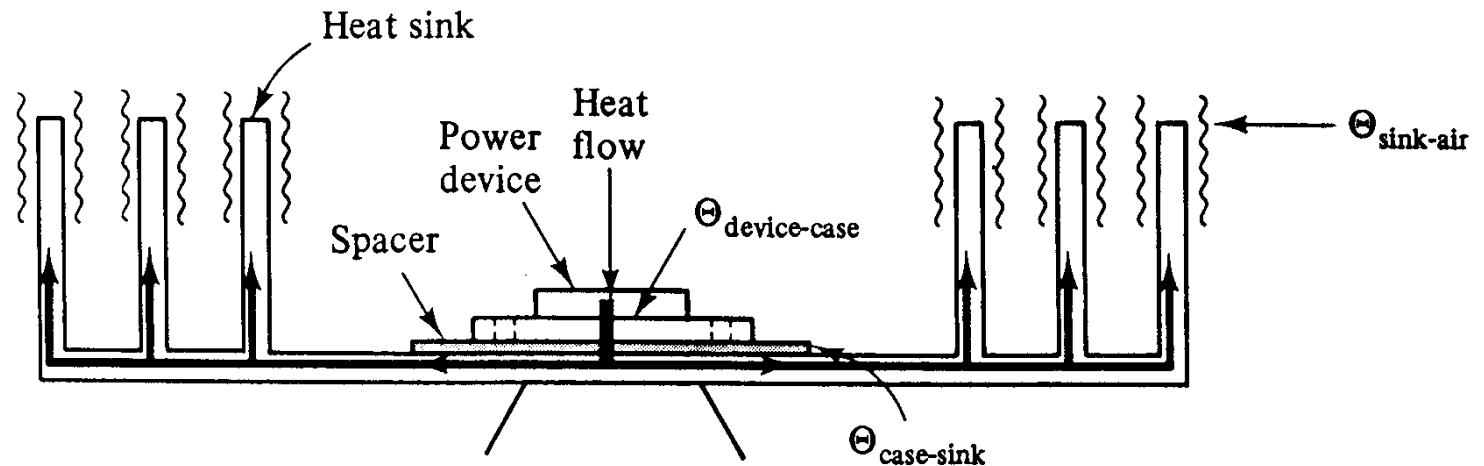
- In thermal equilibrium the electrical power dissipated will equal the heat flow. We can then determine the operating temperature of the device



Example:

A power BJT for which  $\theta_{\text{DEVICE-CASE}} = 4^\circ \text{C/W}$  is mounted on a heat sink with  $\theta_{\text{SINK-AIR}} = 5^\circ \text{C/W}$ . The mounting uses a 0.2 mm thick mica spacer which introduces an additional thermal resistance of  $1^\circ \text{C/W}$  between the transistor case and heat sink. If the BJT carries an average current ( $i_C$ ) of 1 A at an average voltage of  $v_{\text{CE}} = 10 \text{ V}$ . Determine the operating temperature of the semiconductor, transistor case and heat sink. Assume  $T_{\text{AIR}} = 25^\circ \text{C}$ . Neglect power dissipated in the base emitter junction of the BJT.

**Figure 12.27**  
Heat flow from power device to ambient air via heat sink.



Solution:

$$P_{ELEC} = i_C v_{CE} = (1A)(10V) = 10W$$

Since  $P_{ELEC} = P_{OUT}$  In thermal equilibrium

$$\begin{aligned} T_{DEVICE} &= T_{AIR} + P_{OUT} (\theta_{DEVICE-CASE} + \theta_{C-S} + \theta_{S-A}) \\ &= 25^\circ C + (10W)(4^\circ C/W + 1^\circ C/W + 5^\circ C/W) \\ &= 125^\circ C \end{aligned}$$

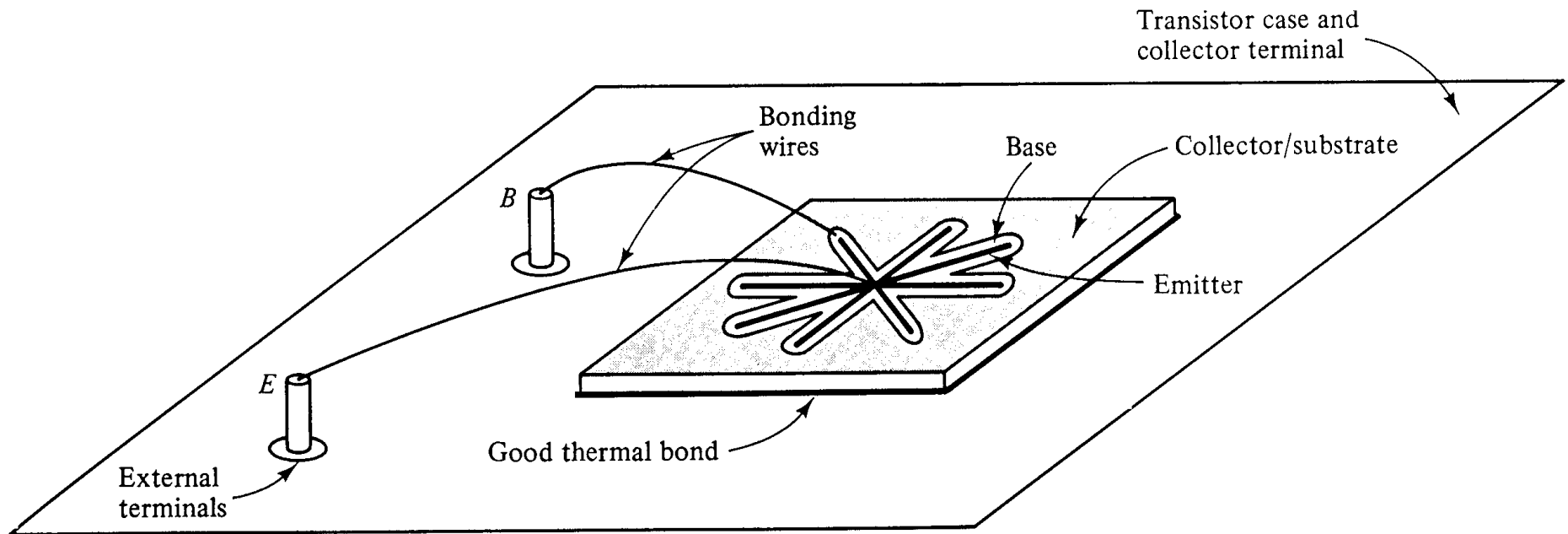
Similarly

$$T_{CASE} = T_{AIR} + P_{OUT} (\theta_{C-S} + \theta_{S-A}) = 85^\circ C$$

$$T_{SINK} = T_{AIR} + P_{OUT} \theta_{S-A} = 75^\circ C$$

# Power BJT

Figure 12.29 Physical geometry of a typical discrete power BJT.

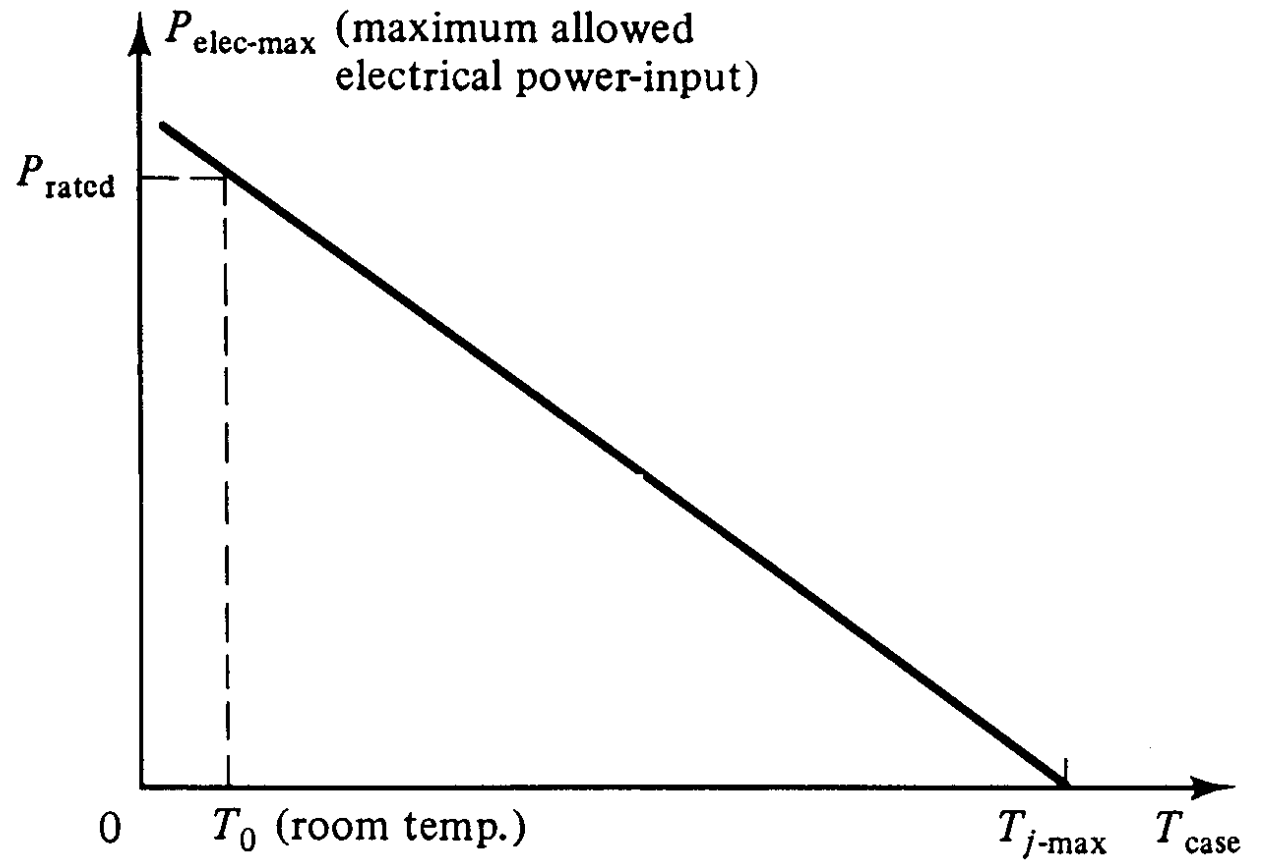


- “Star” shaped pattern of transistor increases surface area of base collector junction where most of the power is dissipated
- Manufacturer usually specifies a maximum temperature  $T_{j-MAX}$  at which the device can be operated without causing permanent damage

$$P_{ELEC-MAX} = \frac{T_{j-MAX} - T_{CASE}}{\theta_{DEVICE-CASE}}$$

- A plot of  $P_{ELEC-MAX}$  versus  $T_{CASE}$  is called a power derating curve of the transistor
- The rated power of the device is the maximum electrical power when the case temperature is equal to the room temperature

**Figure 12.30**  
Power transistor  
derating curve.



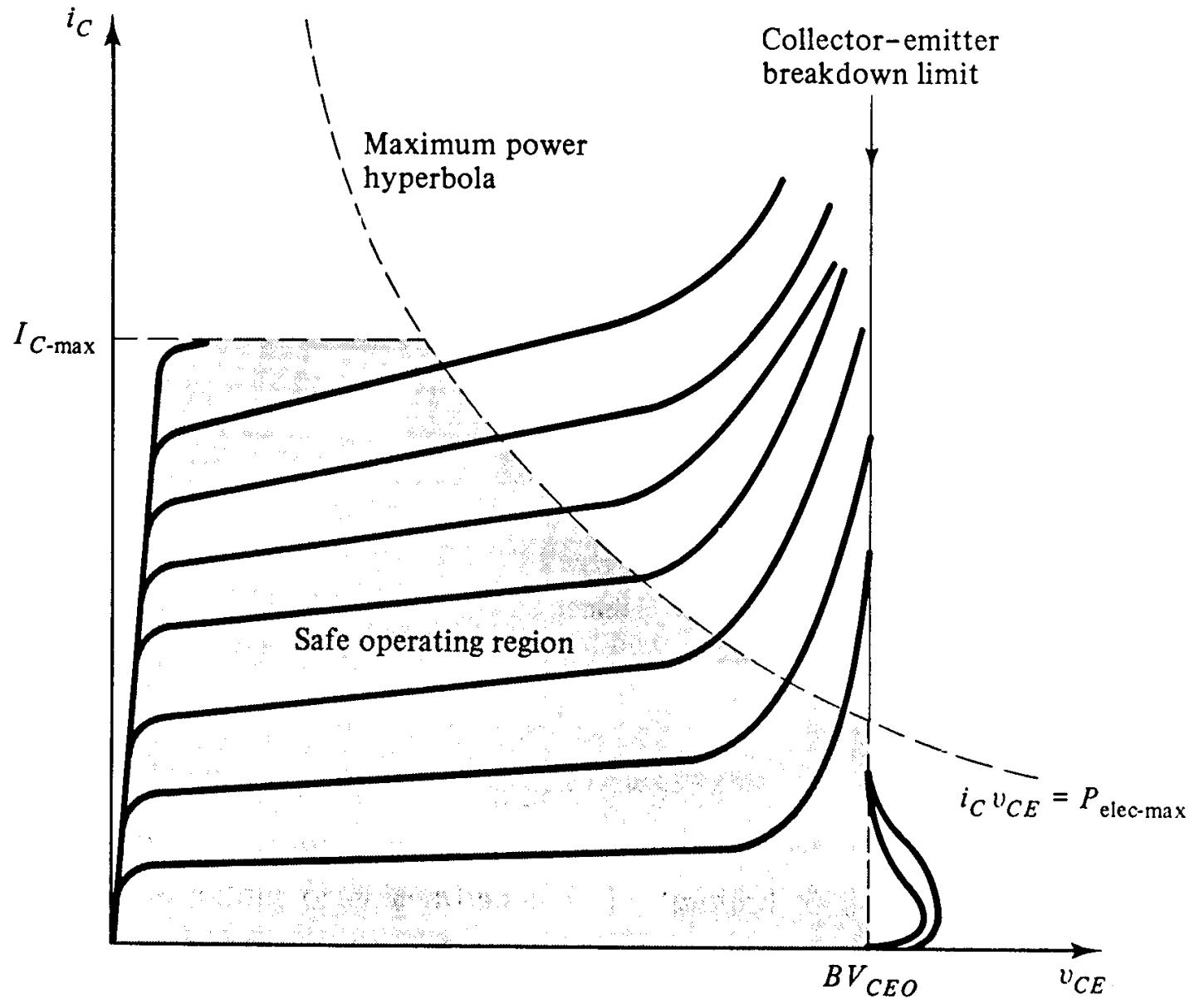
- The maximum safe operating power hyperbola is defined for the BJT by the relation

$$P_{\text{ELEC-MAX}} = i_{\text{C}} v_{\text{CE}}$$

- Note that there are other limiting specs. (e.g.  $I_{\text{C-MAX}}$ ,  $BV_{\text{CEO}}$ ) which may be more stringent than the power operating specs.

**Figure 12.31**

Safe operating region of a BJT is defined by the maximum power hyperbola, the maximum collector current  $I_{C-max}$ , and the collector-emitter breakdown voltage  $BV_{CEO}$ .

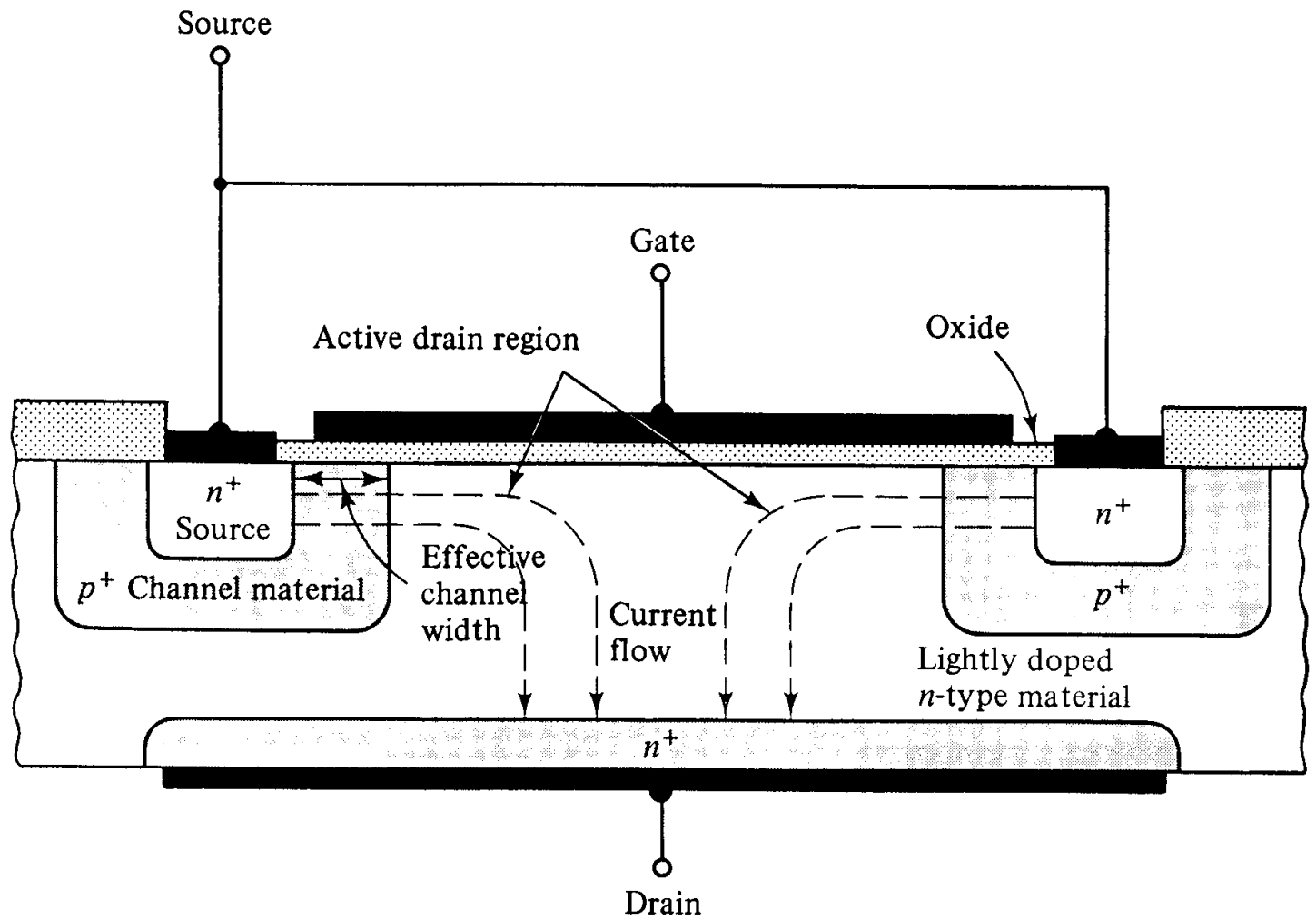


# Power MOSFETs

- Power MOSFETs are also capable of dissipating large amounts of power
- The planar MOSFET geometry is no longer suitable due to avalanche breakdown in the short channel between drain and source
- Common approach is to use a double diffused vertical MOSFET or DMOS transistor

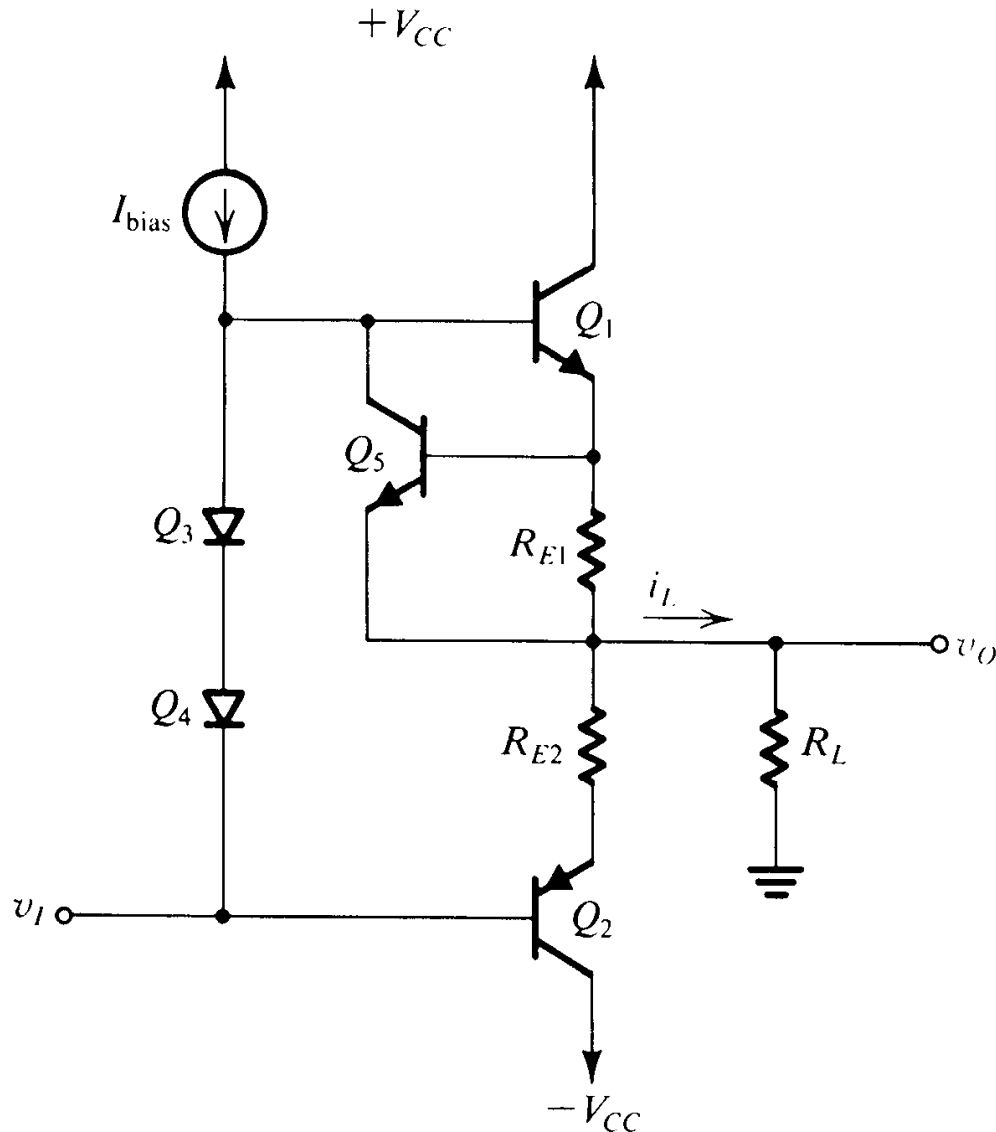


**Figure 12.32**  
Physical geometry of a  
high-power double-  
diffused vertical  
MOSFET (DMOS)  
device.



# Short Circuit Protection and Thermal Shutdown

- The figure below shows a class AB output stage equipped with protection against the effects of short circuiting the output while the stage is sourcing current



**Fig. 9.28** A class AB output stage with short-circuit protection. The protection circuit shown operates in the event of an output short circuit while  $v_O$  is positive.

- In addition to short circuit protection most IC power amplifiers are usually equipped with a circuit that shuts the amplifier down if a safe temperature is exceeded

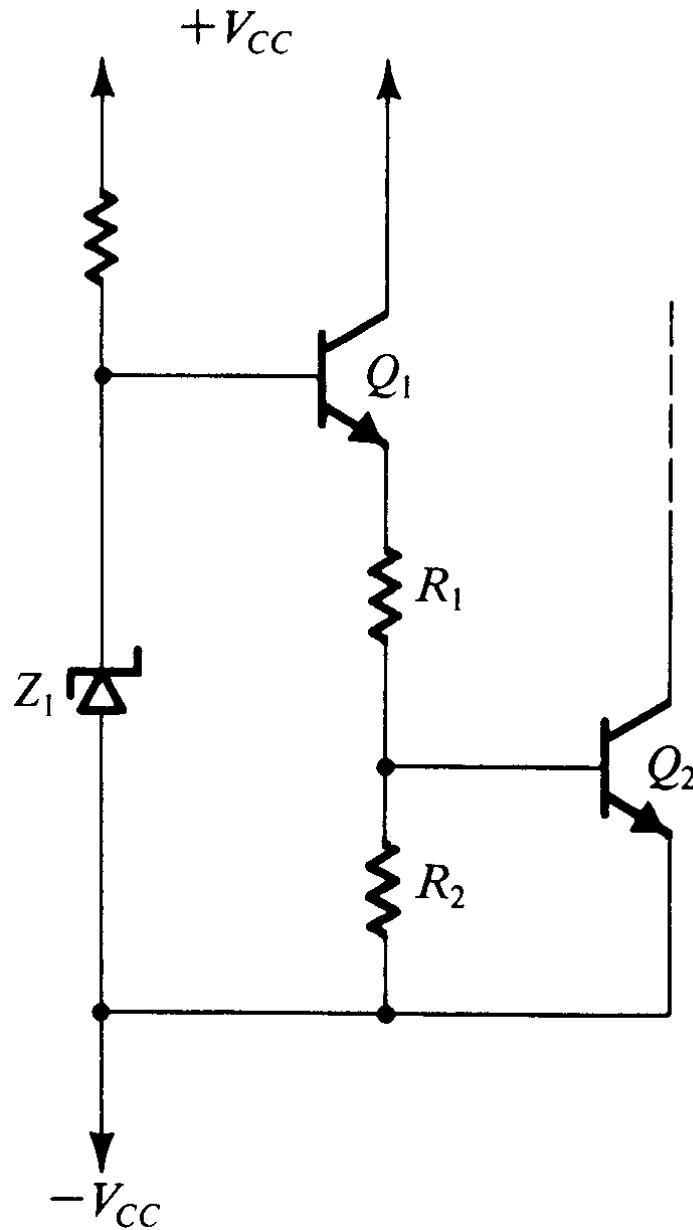
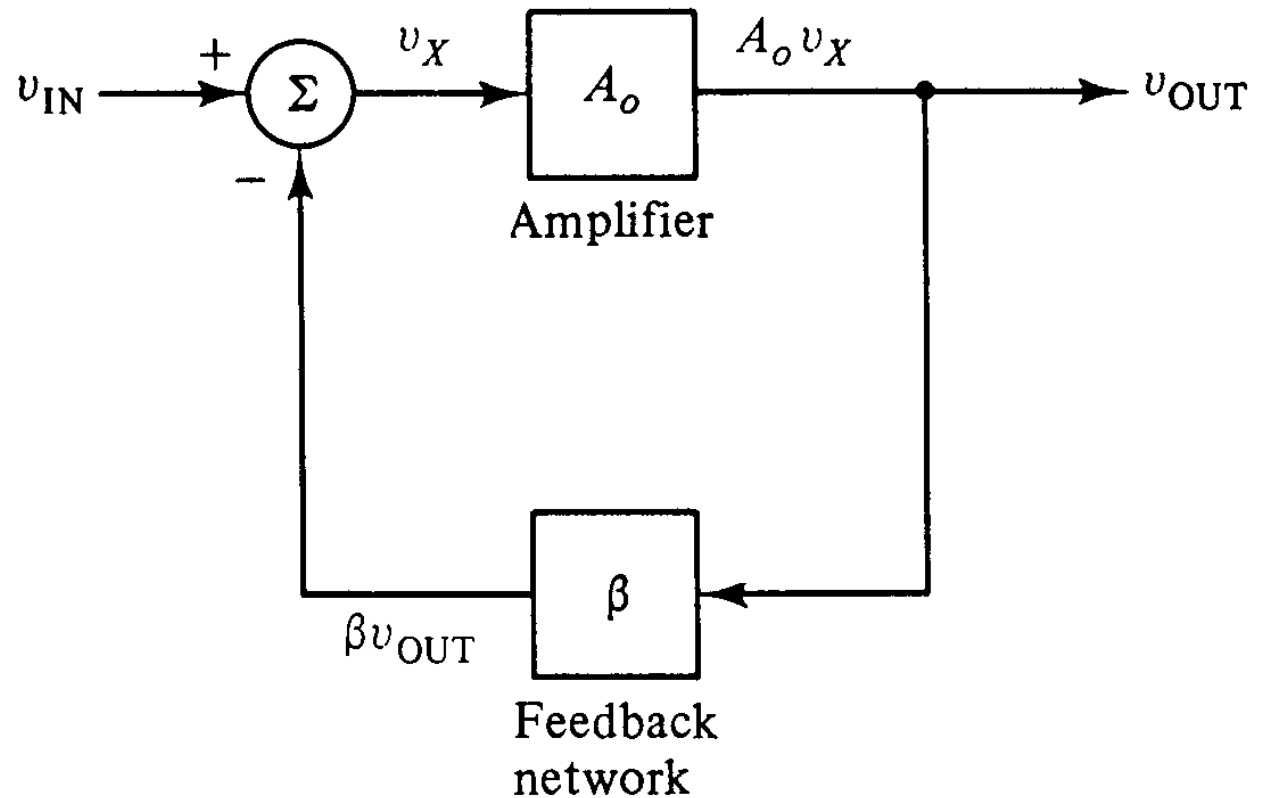


Fig. 9.29 Thermal shutdown circuit.

# Feedback and Stability

- An opamp that incorporates negative feedback can be represented by the following block diagram

**Figure 14.1**  
Block diagram  
representation of  
negative feedback.



- The “amplifier” block multiplies the voltage  $v_x$  by  $A_o$  which represents the open loop gain of the opamp
- The output of the amplifier is fed into the feedback block where it is multiplied by  $\beta$ . The feedback block represents the components that form the feedback network
- The output of the feedback block is subtracted from  $v_{IN}$  and the result is fed back into the amplifier block as  $v_x$

$$v_{OUT} = A_o v_x = A_o (v_{IN} - \beta v_{OUT})$$

$$v_{OUT} = v_{IN} \left[ \frac{A_o}{1 + A_o \beta} \right] = v_{IN} \frac{1}{\left( \frac{1}{A_o} + \beta \right)}$$

- The factor multiplying  $v_{IN}$  is called the closed loop gain. In the limit  $A_o \gg 1$

$$v_{OUT} \cong v_{IN} \frac{1}{\beta}$$